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CY91F463NA/F463NC/V460A

FR60, CY91460N Series, 32-bit Microcontroller Datasheet

CY91F463NA is a line of the general-purpose 32-bit RISC microcontrollers designed for embedded control applications which require high-speed real-time processing, such as consumer devices and on-board vehicle systems. CY91F463NA uses the FR60 CPU which is compatible with the FR CPUs.

CY91F463NA contains the LIN-USART and CAN controllers.

Note: CY91F463NC improved the features of CY91F463NA and updated the sector map for the flash memory. Please select CY91F463NC for the future development.

Features

FR60 CPU

- 32-bit RISC, load/store architecture, five-stage pipeline
- Maximum operating frequency: 80 MHz (oscillator frequency: 4 MHz; oscillator frequency multiplier: 20 (PLL clock multiplication method))
- 16-bit fixed-length instructions (basic instructions)
- Instruction execution speed: 1 instruction per cycle
- Instructions including memory-to-memory transfer, bit manipulation instructions, and barrel shift instructions: Instructions suitable for embedded applications
- Function entry/exit instructions and register data multi load store instructions: Instructions supporting C language
- Register interlock function: Facilitating assembly-language coding
- Built-in multiplier with instruction-level support

Signed 32-bit multiplication: 5 cycles Signed 16-bit multiplication: 3 cycles

- Interrupt (PC/PS saving): 6 cycles (16 priority levels)
- Harvard architecture allowing program access and data access to be executed simultaneously
- Instructions compatible with the FR family

Internal Peripheral Resources

- Flash memory capacity: 288 Kbytes
- Internal RAM capacity: 8 Kbytes (Data RAM) + 2 Kbytes (Instruction/data RAM)
- General-purpose port: Maximum 48 ports
- DMAC (DMA Controller)

Maximum of 5 channels for able to operate simultaneously

2 transfer sources (internal peripheral/software)

Activation source can be selected by programs

Addressing mode specifies full 32-bit addresses (increment/decrement/fixed)

Transfer mode (burst transfer/step transfer/block transfer)

Transfer data size selectable from 8/16/32-bit

Multi-byte transfer capable (by programs)

DMAC descriptor in I/O areas (200_H to 240_H, 1000_H to 1024_H)

■ A/D converter (sequential comparison)

10-bit resolution: 8 channels

Conversion time: 1 μ s (using at 5 V), 3 μ s (using at 3.3 V)

- External interrupt inputs: 10 channels
- Bit search module (for REALOS)

Function to search from the MSB (most significant bit) for the position of the first "0", "1" or changed bit in a word

■ LIN-USART (full duplex double buffer): 4 channels

Clock synchronous/asynchronous selectable

Sync-break detection

Internal dedicated baud rate generator

■ I²C bus interface (Supports 400 kbps): 2 channels

Master/slave transmission and reception

Arbitration function, clock synchronization function

■ CAN controller (C-CAN): 2 channels

Maximum transfer speed: 1 Mbps

32 transmission/reception message buffers

- 16-bit PPG timer: 8 channels
- 16-bit reload timer: 4 channels + 1 channel (exclusive A/D converter)
- 16-bit free-run timer: 4 channels
- Input capture: 4 channels

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- Output compare: 4 channels
- 8/16-bit up/down counter: 2 channels (8-bit)/1channel (16-bit)
- Watchdog timer
- Real-time clock
- Low-power consumption mode: Sleep/stop mode function

Package: LQFP-64 (LQG064) CMOS 0.18 µm technology

3.3 V only power supplies or 5 V only power supplies

Operating temperature range:

- -40°C to $+85^{\circ}\text{C}$ (using at 5 V)
- -40°C to +105°C (using at 3.3 V)

Document Number: 002-04604 Rev. *C Page 2 of 81



Contents

Product Lineup	4
Pin Assignment	6
Pin Description	7
Power Supply/GND Pins	9
I/O Circuit Type	10
Precautions for Handling The Devices	14
Precautions for Product Design	
Precautions for Package Mounting	
Precautions for Use Environment	17
Handling Devices	18
Notes on Debugger	20
Execution of the RETI Command	20
Break Function	20
Operand Break	
Notes on PS Register	20
Block Diagram	21
CPU and Control Unit	22
Features	22
Internal Architecture	23
Programming Model	24
Registers	25
Mode Setting	28
Mode Pins	
Mode Register (MODR)	28

Recommended Setting	29
Setting of PLL and Clock Gear	29
Setting of Flash Memory Controller	
Setting of Clock Modulator	
Memory Space	34
Memory space	
Memory Map	
Flash Memory Sector Configuration	36
I/O Map	37
Interrupt Source Table	56
Electrical Characteristics	60
Absolute Maximum Rating	60
Recommended Operating Conditions	
DC Characteristics	
AC Characteristics	
Electrical Characteristics for A/D Converter	
Notes on the A/D Converter	
Definition of A/D Converter Terms	
Flash Memory Program/Erase Characteristics	
Ordering Information	77
Package Dimension	78
Main Changes in This Edition	79
Document History	
Sales, Solutions, and Legal Information	81



1. Product Lineup

Part Number Parameter	CY91V460A	CY91F463NA CY91F463NC			
Max core frequency (CLKB)	80 MH	z			
Max resource frequency (CLKP)	40 MH	z			
Max external bus frequency (CLKT)	40 MHz	-			
Max CAN frequency (CLKCAN)	20 MH	z			
Technology	0.35 μm	0.18 μm			
Watchdog Timer	Yes	No			
Watchdog Timer (CR oscillator)	Yes (disengageable)	Yes			
Bit search	Yes				
Reset input (INITX)	Yes				
Hardware standby input (HSTX)	Yes	No			
Clock modulator	Yes				
Low-power mode	Yes				
DMAC	5 channels				
MAC (μDSP)	No				
MMU/MPU	MPU (16 channels) ^[1]	MPU (4 channels) ^[1]			
Flash memory	Emulation SRAM 32-bit read data	288 Kbytes			
Flash protection	-	Yes			
Data RAM	64 Kbytes	8 Kbytes			
Instruction/data RAM	64 Kbytes	2 Kbytes			
Flash-cache (instruction cache)	16 Kbytes	4 Kbytes			
Boot-ROM/BI-ROM	4 Kbytes fixed	4 Kbytes (BI-ROM)			
Real-time clock	1 channe	els			
Free-run timer	8 channels	4 channels			
ICU	8 channels	4 channels			
OCU	8 channels	4 channels			
16-bit reload timer	8 channels	4 channels + 1 channel			
16-bit PPG	16 channels	8 channels			

Document Number: 002-04604 Rev. *C Page 4 of 81



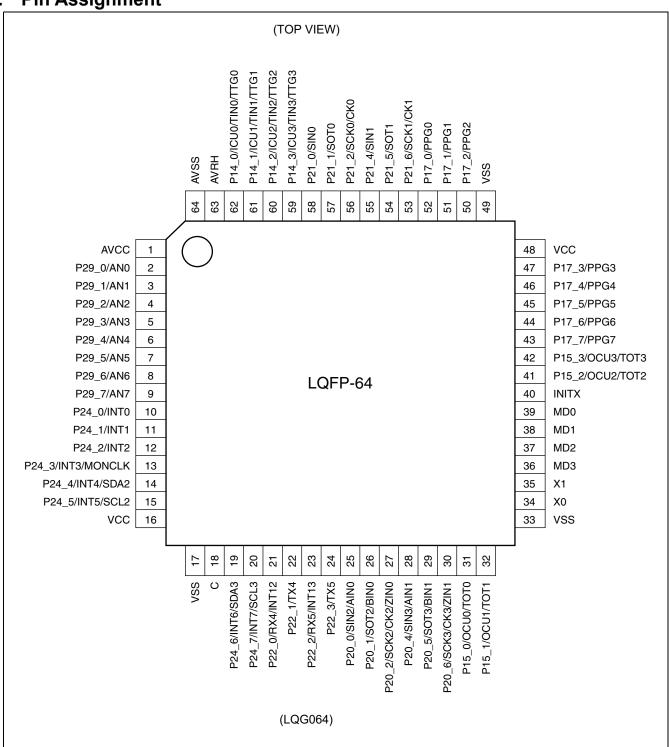
Part Number Parameter	CY91V460A	CY91F463NA CY91F463NC		
16-bit PFM	1 channel	No		
Sound Generator	1 channel	No		
8/16-bit up/down counter	4 channels (8-bit) / 2 channels (16-bit)	2 channels (8-bit) /1 channel (16-bit)		
C_CAN	6 channels (128 message buffers)	2 channels (32 message buffers)		
LIN-USART	4 channels + 4 channels (FIFO) + 8 channels	4 channels		
I ² C (400 kbps)	4 channels	2 channels		
FR external bus	Yes (32-bit address, 32-bit data)	No		
External interrupt	16 channels	10 channels		
NMI interrupts	Yes	No		
Stepping motor controller (SMC)	6 channels	No		
LCD controller (40 × 4)	1 channel	No		
10-bit A/D converter	32 channels	8 channels		
Alarm comparator	2 channels	No		
Clock supervisor	Yes	No		
Main clock oscillator	4 MH	lz		
Sub clock oscillator	32 kHz	-		
CR oscillator	100 kHz	100 kHz / 2 MHz		
PLL	× 20)		
DSU4	Yes	No		
EDSU	Yes (32 BP) ^[1]	Yes (8 BP) ^[1]		
Power supply voltage	3 V / 5	5 V		
Regulator	Yes	3		
Power consumption	n.a.	< 700 mW		
Temperature range (T _A)	0 °C to +70°C	- 40 °C to + 105°C		
Package	BGA-660	LQFP-64		

^{1.} MPU channels use EDSU breakpoint registers (shared operation between MPU and EDSU).

Document Number: 002-04604 Rev. *C Page 5 of 81



2. Pin Assignment



Page 7 of 81



3. Pin Description

P29_0 to P29_7	Pin No.	Pin Name	I/O	I/O Circuit Type ^[1]	Function		
AN0 to AN7 P24_0 to P24_2 INT0 to INT2 P24_3 INT3 INT3 MONCLK P24_4 INT4 INT4 INT4 INT4 Analog input pins for A/D converter General-purpose input/output ports External interrupt input pins General-purpose input/output port External interrupt input pins Clock monitor output pin General-purpose input/output port External interrupt input pins Clock monitor output pin General-purpose input/output port External interrupt input pin I'C External interrupt input pin I'C bus data input/output pin	2 to 0	P29_0 to P29_7	1/0	В	General-purpose input/output ports		
10 to 12 INT0 to INT2 I/O A External interrupt input pins P24_3 General-purpose input/output port INT3 I/O A External interrupt input pins MONCLK Clock monitor output pin P24_4 General-purpose input/output port INT4 I/O C External interrupt input pin General-purpose input/output port External interrupt input pin General-purpose input/output port External interrupt input pin I/O C External interrupt input pin I/O DESTRUCTION OF THE INPUT PIN	2109	AN0 to AN7	1/0	Ь	Analog input pins for A/D converter		
INT0 to INT2 P24_3 INT3 INT3 I/O A External interrupt input pins General-purpose input/output port External interrupt input pins Clock monitor output pin P24_4 INT4 INT4 IVO C External interrupt input pins Clock monitor output pin General-purpose input/output port External interrupt input pin IPC bus data input/output pin	10 to 10	P24_0 to P24_2	1/0	Δ.	General-purpose input/output ports		
13 INT3 I/O A External interrupt input pins MONCLK Clock monitor output pin General-purpose input/output port INT4 I/O C External interrupt input pin SDA2 IVO C IVO C External interrupt input pin I ² C bus data input/output pin	10 10 12	INT0 to INT2	1/0	A	External interrupt input pins		
MONCLK Clock monitor output pin P24_4 INT4 INT4 SDA2 Clock monitor output pin General-purpose input/output port External interrupt input pin I ² C bus data input/output pin	13	P24_3			General-purpose input/output port		
P24_4 INT4 INT4 SDA2 General-purpose input/output port External interrupt input pin I ² C bus data input/output pin		INT3	I/O	I/O A External interrupt input pins			
14 INT4 I/O C External interrupt input pin SDA2 I ² C bus data input/output pin		MONCLK			Clock monitor output pin		
SDA2 I ² C bus data input/output pin		P24_4			General-purpose input/output port		
	14	INT4	I/O	С	External interrupt input pin		
D24 5		SDA2			I ² C bus data input/output pin		
General-purpose input/output port		P24_5			General-purpose input/output port		
15 INT5 I/O C External interrupt input pin	15	INT5	I/O	С	External interrupt input pin		
SCL2 I ² C bus clock input/output pin		SCL2			I ² C bus clock input/output pin		
P24_6 General-purpose input/output port		P24_6			General-purpose input/output port		
19 INT6 I/O C External interrupt input pin	19	INT6	I/O	С	External interrupt input pin		
SDA3 I ² C bus data input/output pin		SDA3			I ² C bus data input/output pin		
P24_7 General-purpose input/output port		P24_7					
20 INT7 I/O C External interrupt input pin	20	INT7	I/O	С	External interrupt input pin		
SCL3 I ² C bus clock input/output pin		SCL3			I ² C bus clock input/output pin		
P22_0 General-purpose input/output port		P22_0			General-purpose input/output port		
21 RX4 I/O A RX input pin of CAN4	21		I/O	А	RX input pin of CAN4		
INT12 External interrupt input pin		INT12			External interrupt input pin		
P22_1 General-purpose input/output port		P22_1			General-purpose input/output port		
TX4 I/O A TX output pin of CAN4	22	TX4	I/O	A	TX output pin of CAN4		
P22_2 General-purpose input/output port		P22_2			General-purpose input/output port		
23 RX5 I/O A RX input pin of CAN5	23	RX5	I/O	А	RX input pin of CAN5		
INT13 External interrupt input pin		INT13			External interrupt input pin		
P22_3 General-purpose input/output port		P22_3			General-purpose input/output port		
24 TX5 I/O A TX output pin of CAN5	24	TX5	I/O	A	TX output pin of CAN5		
P20_0 General-purpose input/output port		P20_0			General-purpose input/output port		
25 SIN2 I/O A Data input pin of LIN-USART2	25	SIN2	I/O	Α	Data input pin of LIN-USART2		
AIN0 Up/down counter input pin		AIN0			Up/down counter input pin		
P20_1 General-purpose input/output port		P20_1			General-purpose input/output port		
26 SOT2 I/O A Data output pin of LIN-USART2	26		I/O	Α	Data output pin of LIN-USART2		
BIN0 Up/down counter input pin		BIN0			Up/down counter input pin		
P20_2 General-purpose input/output port		P20_2			1 1		
SCK2 Clock input/output pin of LIN-USART2	0=	SCK2			Clock input/output pin of LIN-USART2		
27 CK2 I/O A Free-run timer input pin	2/	CK2	I/O	A	Free-run timer input pin		
ZIN0 Up/down counter input pin		ZIN0			Up/down counter input pin		
P20_4 General-purpose input/output port		P20_4			General-purpose input/output port		
28 SIN3 I/O A Data input pin of LIN-USART3	28		I/O	Α [
AIN1 Up/down counter input pin		AIN1			1 1		



Pin No.	Pin Name	I/O	I/O Circuit Type ^[1]	Function			
	P20_5			General-purpose input/output port			
29	29 SOT3		Α	Data output pin of LIN-USART3			
	BIN1	BIN1		Up/down counter input pin			
	P20_6			General-purpose input/output port			
00	SCK3	1/0		Clock input/output pin of LIN-USART3			
30	CK3	- I/O	Α	Free-run timer input pin			
	ZIN1			Up/down counter input pin			
	P15_0			General-purpose input/output port			
31	OCU0	I/O	Α	Output compare output pin			
	TOT0			Reload timer output pin			
	P15_1			General-purpose input/output port			
32	OCU1	I/O	Α	Output compare output pin			
	TOT1			Reload timer output pin			
34	X0	-	J	Clock (oscillation) input			
35	X1	-	J	Clock (oscillation) output			
36	MD3	I	I	Mode setting pin			
37	MD2	ı	G	Mode setting pin			
38	MD1	I	G	Mode setting pin			
39	MD0	ı	G	Mode setting pin			
40	INITX	I	Н	External reset input			
	P15_2			General-purpose input/output port			
41	OCU2	I/O	Α	Output compare output pin			
	TOT2			Reload timer output pin			
	P15_3			General-purpose input/output port			
42	OCU3	I/O	Α	Output compare output pin			
	ТОТ3			Reload timer output pin			
43 to 47,	P17_7 to P17_0		_	General-purpose input/output ports			
50 to 52	PPG7 to PPG0	I/O	Α	PPG timer output pins			
	P21_6			General-purpose input/output port			
53	SCK1	I/O	Α	Clock input/output pin of LIN-USART1			
	CK1			Free-run timer input pin			
	P21_5			General-purpose input/output port			
54	SOT1	I/O	Α	Data output pin of LIN-USART1			
	P21_4			General-purpose input/output port			
55	SIN1	I/O	Α	Data input pin of LIN-USART1			
	P21_2			General-purpose input/output port			
56	SCK0	I/O	Α	Clock input/output pin of LIN-USART0			
	CK0	1		Free-run timer input pin			
	P21_1	1/2	_	General-purpose input/output port			
57	SOT0	I/O	Α	Data output pin of LIN-USART0			
	P21_0		_	General-purpose input/output port			
58	SIN0	I/O	Α	Data input pin of LIN-USART0			
	1						



Pin No.	Pin Name	I/O	I/O Circuit Type ^[1]	Function	
	P14_3			General-purpose input/output port	
59	ICU3	1/0	1	Input capture input pin	
59	TIN3	1/0	A External trigger input pin of reload timer		
	TTG3			PPG timer input pin	
	P14_2			General-purpose input/output port	
60	ICU2	1/0	I/O A	Input capture input pin	
00	TIN2	1/0		External trigger input pin of reload timer	
	TTG2			PPG timer input pin	
	P14_1		I/O A	General-purpose input/output port	
61	ICU1	1/0		Input capture input pin	
01	TIN1	1/0		External trigger input pin of reload timer	
	TTG1			PPG timer input pin	
	P14_0			General-purpose input/output port	
62	ICU0	1/0	^	Input capture input pin	
02	TIN0	1/0	Α	External trigger input pin of reload timer	
	TTG0			PPG timer input pin	

^{1.} For I/O circuit type, refer to "I/O Circuit Type".

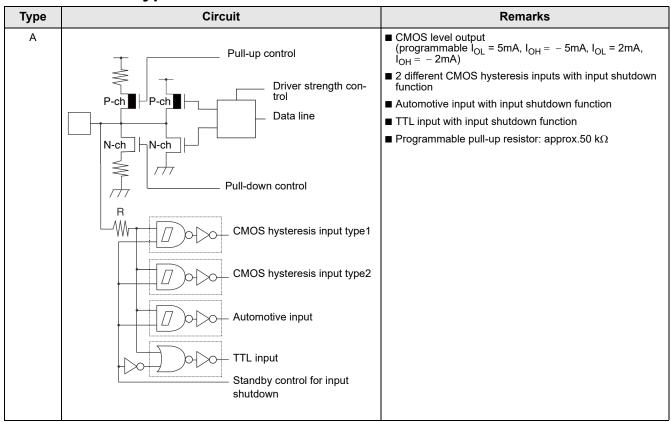
3.1 Power Supply/GND Pins

Pin No.	Pin Name	I/O	Function	
17, 33, 49	VSS	-	GND pins	
16, 48	VCC	-	- 3.3 V/5 V power supply pins	
64	AVSS	- Analog GND pin for A/D converter		
1	AVCC	- 3.3 V/5 V power supply pin for A/D converter		
63	AVRH	- Reference power supply pin for A/D converter		
18	С	- Capacitor connection pin for internal regulator		

Document Number: 002-04604 Rev. *C Page 9 of 81



4. I/O Circuit Type





Туре	Circuit	Remarks
В	Pull-up control Driver strength control Data line Pull-down control R CMOS hysteresis input type1 CMOS hysteresis input type2 Automotive input Standby control for input shutdown Analog input	 ■ CMOS level output (programmable I_{OL} = 5 mA, I_{OH} = −5 mA, I_{OL} = 2 mA, I_{OH} = −2 mA) ■ 2 different CMOS hysteresis inputs with input shutdown function ■ Automotive input with input shutdown function ■ TTL input with input shutdown: approx.50 kΩ ■ Analog input



Туре	Circuit	Remarks
С	Pull-up control	■ CMOS level output (I _{OL} = 3 mA, I _{OH} = −3 mA) ■ 2 different CMOS hysteresis inputs with input shutdown function
	P-ch P-ch P-ch Data line	 ■ Automotive input with input shutdown function ■ TTL input with input shutdown function ■ Programmable pull-up resistor: approx.50 kΩ
	Pull-down control	
	CMOS hysteresis input type1	
	CMOS hysteresis input type2	
	Automotive input	
	Standby control for input shutdown	



Туре	Circuit	Remarks
G	R CMOS level input	■ MASK ROM and evaluation device: CMOS level input ■ Flash device: □ CMOS level input □ 12 V resistant (for MD [2:0])
н	Pull-up resistor R CMOS Hysteresis inpu	■ CMOS hysteresis input ■ Pull-up resistor value: approx.50 kΩ
I	R CMOS Hysteresis inpu Pull-down resistor	■ CMOS hysteresis input ■ Pull-down resistor value: approx.50 kΩ
J	X1 Xout X0 Standby control signal	Oscillation circuit



5. Precautions for Handling The Devices

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

5.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

■ Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ Recommended Operating Conditions

The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges. Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their Cypress representatives beforehand.

■ Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such over voltage or over-current conditions at the design stage.

2. Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device. Therefore, avoid this type of connection.

3. Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

■ Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

Note:

The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (a) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (b) Be sure that abnormal current flows do not occur during the power-on sequence.

■ Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

■ Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Document Number: 002-04604 Rev. *C Page 14 of 81



■ Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION:

Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, submarine repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with Cypress sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

Document Number: 002-04604 Rev. *C Page 15 of 81



5.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mounting type. In either case, quality assurance of heat resistance are applied for mounting under the Cypress's recommended conditions only at the soldering stage. For detailed information on mount conditions, contact the sales representative.

■ Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket. Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions. If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

■ Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges. You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

■ Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (a) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (b) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between $+5^{\circ}$ C to $+30^{\circ}$ C.
- (c) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (d) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

■ Bakino

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

■ Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

- (a) Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
- (b) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (c) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ). Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
- (d) Ground all fixtures and instruments, or protect with anti-static measures.
- (e) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

Document Number: 002-04604 Rev. *C Page 16 of 81



5.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above. For reliable performance, do the following:

- 1. Humidity
 - Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
- 2. Discharge of Static Electricity
 - When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
- 3. Corrosive Gases, Dust, or Oil
 - Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
- 4. Radiation, Including Cosmic Radiation
 - Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
- 5. Smoke, Flame
 - **Note**: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with Cypress sales representatives.

Document Number: 002-04604 Rev. *C Page 17 of 81



6. Handling Devices

■ Power supply pins

Because there are multiple VCC and VSS pins, respective pins at the same potential are interconnected to prevent malfunctions such as latch-up. However, you must connect the pins externally to the power supply and ground lines to reduce the electro-magnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating. Furthermore, the current supply source should be connected to the VCC and VSS pins of the device at a low impedance.

It is recommended to connect a ceramic bypass capacitor of approximately 0.1 μ F as a bypass capacitor between the V_{CC} and V_{SS} near this device.

■ Crystal oscillator circuit

Noise in proximity to the X0 and X1 pins can cause the device to malfunction. Printed circuit boards should be designed so that the X0 and X1 pins, crystal oscillator (or ceramic oscillator), and bypass capacitors connected to ground are located near the device and ground.

It is recommended that the printed circuit board artwork be designed such that the X0 and X1 pins are surrounded by ground plane for the stable operation.

Please request the oscillator manufacturer to evaluate the oscillational characteristics of the crystal and this device.

■ Mode pins (MD0 to MD3)

Connect them directly to VCC or VSS. To prevent the device from entering test mode accidentally due to noise, minimize the lengths of the patterns between each mode pin and VCC or VSS on the printed circuit board as much as possible and connect them at a low impedance. When used pulling down, design your circuit not to generate noises with a resistance 1 $k\Omega$ or less. Test your circuit and confirm that there is no problem.

■ Operation at power-on

At power-on, it is necessary to make the terminal INITX "L" level.

Maintain the "L" level input to the INITX pin for the duration of the stabilization wait time immediately after the power on to ensure the stabilization wait time as required by the oscillator circuit.

■ Note on oscillator input at power-on

At power-on, ensure that the clock is input until the oscillator stabilization wait time has elapsed.

■ Built-in regulator

As this series includes built-in step-down regulators, always connect a bypass capacitor of 4.7 μ F or more to the C pin for use by the regulator.

■ Notes on power on/off

Connect/disconnect the power supply pins when power on/off, or turn on/off in the following order.

Power on : VCC \rightarrow AVCC, AVRH Power off : AVCC, AVRH \rightarrow VCC

■ Precautions for the STOP mode

Set 1 to the bit 0 (OSCD1) of STCR register. When shifting to the STOP mode, a regulator switches to the stand-by regulator (for low-consumption current). Due to the limited drive current, stop the (programming/erasing) access to the A/D converter and Flash before shifting to the STOP mode.

■ Serial communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication. Therefore, design a board so as to avoid noise.

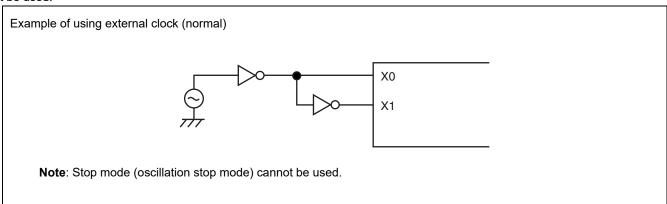
Consider receiving of wrong data when designing the system. For example, apply a checksum to detect an error. If an error is detected, retransmit the data.

Document Number: 002-04604 Rev. *C Page 18 of 81



■ Notes on using external clock

When using the external clock, as a general rule you should simultaneously supply X0 and X1 pins. And also, the clock signal to X0 should be supplied a clock signal with the reverse phase to X1 pins. However, in this case the stop mode (oscillation stop mode) must not be used.



■ Notes on operating in PLL clock mode

If the oscillator is disconnected or the clock input stops when the PLL clock is selected, the microcontroller may continue to operate at the free-running frequency of the self-oscillating circuit of the PLL. However, this self-running operation cannot be guaranteed.



Notes on Debugger

7.1 Execution of the RETI Command

If single-step execution is used in an environment where an interrupt occurs frequently, the corresponding interrupt handling routine will be executed repeatedly to the exclusion of other processing. This will prevent the main routine and the handlers for low priority level interrupts from being executed (For example, if the time-base timer interrupt is enabled, stepping over the RETI instruction will always break on the first line of the time-base timer interrupt handler).

Disable the corresponding interrupts when the corresponding interrupt handling routine no longer needs debugging.

7.2 Break Function

If the range of addresses that cause a hardware break (including event breaks) is set to the address of the current system stack pointer or to an area that contains the stack pointer, execution will break after each instruction regardless of whether the user program actually contains data access instructions.

To prevent this, do not set (word) access to the area containing the address of the system stack pointer as the target of the hardware break (including an event breaks).

7.3 Operand Break

It may cause malfunctions if a stack pointer exists in the area which is set as the DSU operand break. Do not set the access to the areas containing the address of system stack pointer as a target of data event break.

7.4 Notes on PS Register

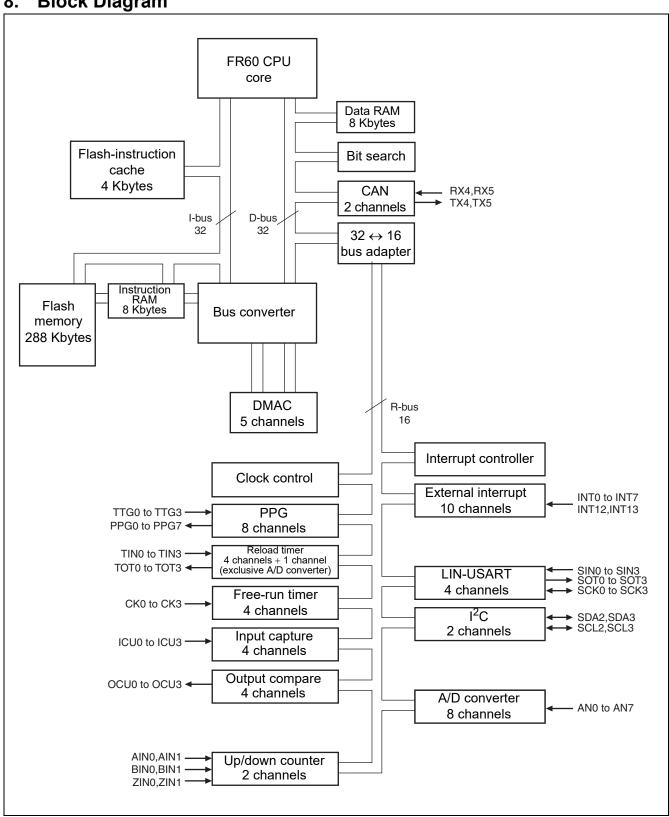
As the PS register is processed in advance by some instructions, when the debugger is being used, the following exception handling may result in execution breaking in an interrupt handling routine or the displayed values of the flags in the PS register being updated. As the microcontroller is designed to carry out reprocessing correctly upon returning from such an EIT event, the operation before and after the EIT always proceeds according to specification.

- The following behavior may occur if any of the following occurs in the instruction immediately after a DIV0U/DIV0S instruction:
 (a) a user interrupt or NMI is accepted; (b) single-step execution is performed; or (c) execution breaks due to a data event or from the emulator menu.
 - □ D0 and D1 flags are updated in advance.
 - ☐ An EIT handling routine (user interrupt/NMI or emulator) is executed.
 - □ Upon returning from the EIT, the DIV0U/DIV0S instruction is executed and the D0 and D1 flags are updated to the same values as those in 1).
- The following behavior occurs when an ORCCR, STILM, MOV Ri or PS instruction is executed to enable a user interrupt or NMI source while that interrupt is in the active state.
 - □ The PS register is updated in advance.
- ☐ An EIT handling routine (user interrupt/NMI or emulator) is executed.
- □ Upon returning from the EIT, the above instructions are executed and the PS register is updated to the same value as in 1).

Document Number: 002-04604 Rev. *C Page 20 of 81



Block Diagram





9. CPU and Control Unit

Internal Architecture

The FR family CPU is a high performance core that is designed based on the RISC architecture with advanced instructions for embedded applications.

9.1 Features

Adoption of RISC architecture

Basic instruction: 1 instruction per cycle

■ General-purpose registers: 32-bit × 16 registers

■ 4 Gbytes linear memory space

■ Multiplier installed

32-bit × 32-bit multiplication: 5 cycles 16-bit × 16-bit multiplication: 3 cycles

■ Enhanced interrupt processing function Quick response speed (6 cycles)

Multiple-interrupt support

Level mask function (16 levels)

■ Enhanced instructions for I/O operation Memory-to-memory transfer instruction Bit processing instruction

■ Basic instruction word length: 16 bits

■ Low-power consumption SLEEP mode/STOP mode

Document Number: 002-04604 Rev. *C Page 22 of 81



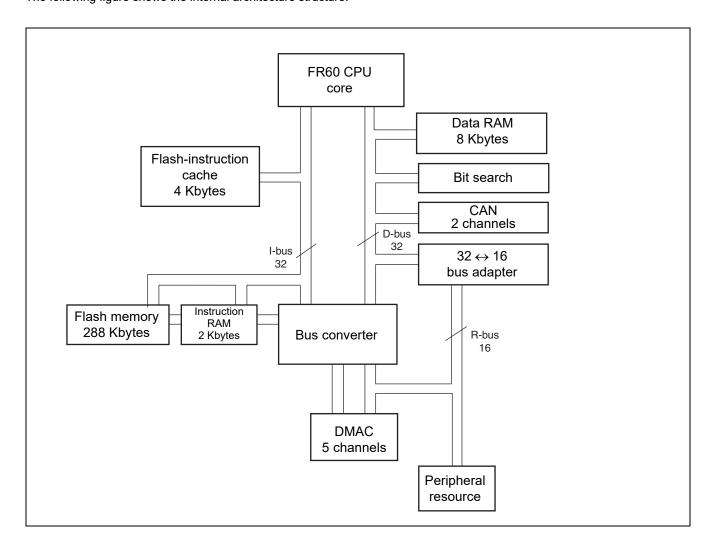
9.2 Internal Architecture

The FR family CPU uses the Harvard architecture in which the instruction bus and data bus are independent of each other.

A 32-bit ↔ 16-bit bus adapter is connected to the 32-bit bus (D-bus) to provide an interface between the CPU and peripheral resources.

A Harvard ↔ Princeton bus converter is connected to both the I-bus and D-bus to provide an interface between the CPU and the bus controller.

The following figure shows the internal architecture structure.





9.3 Programming Model

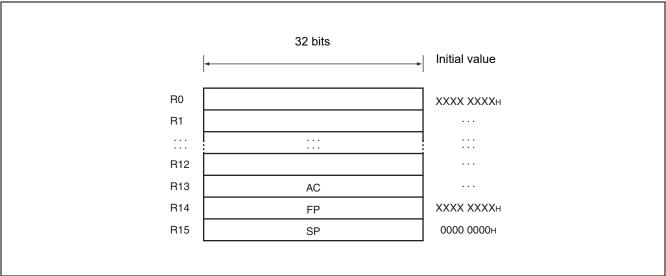
9.3.1 Basic Programming Model

			32 bits			
		-			-	Initial value
	R0 R1					XXXX XXXXH
General-purpose registers	::: R12		:::			
	R13 R14		AC FP			XXXX XXXXH
	R15		SP			0000 0000н
Program counter	PC]
Program status	RS	— ILM	_	SCR	CCR]
Table base register	TBR]
Return pointer	RP]
System stack pointer	SSP]
User stack pointer	USP]
Multiply and divide result registers	MDH MDL					



9.4 Registers

9.4.1 General-purpose Register



Registers R0 to R15 are general-purpose registers. These registers can be used as accumulators for computation operations and as pointers for memory access.

Enhanced commands are provided for some of the 16 registers to enable their use for particular applications.

R13: Virtual accumulator

R14: Frame pointer

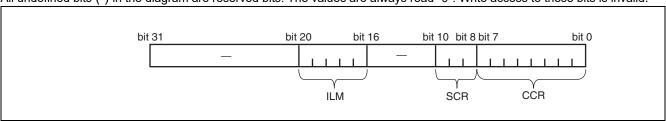
R15: Stack pointer

Initial values at reset are undefined for R0 to R14. The value for R15 is 00000000_H (SSP value).

9.4.2 PS (Program Status)

This register holds the program status, and is divided into three parts, ILM, SCR, and CCR.

All undefined bits (-) in the diagram are reserved bits. The values are always read "0". Write access to these bits is invalid.



Document Number: 002-04604 Rev. *C Page 25 of 81



9.4.3 CCR (Condition Code Register)

	_	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	Initial value
- SV S 1 N Z V C -000XXXXB	[_	SV	S	I	N		V	С	- 000XXXXB

SV: Supervisor

S: Stack flag

I: Interrupt enable flag

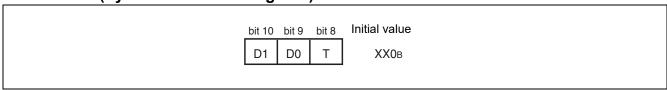
N: Negative enable flag

Z: Zero flag

V: Overflow flag

C: Carry flag

9.4.4 SCR (System Condition Register)



Flag for step multiplication (D1, D0)

This flag stores interim data during execution of step multiplication.

Step trace trap flag (T)

This flag indicates whether the step trace trap is enabled or disabled.

The step trace trap function is used by emulators. When an emulator is in use, it cannot be used in execution of user programs.

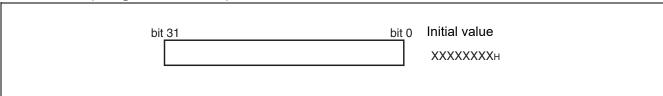
9.4.5 ILM (Interrupt Level Mask Register)

bit 20	bit 19 bi	it 18 bit 17	bit 16	nitial value
ILM4	ILM3 IL	LM2 ILM1	ILM0	01111в
				_

This register stores interrupt level mask values, and the values stored in ILM4 to ILM0 are used for level masking.

The register is initialized to value "01111_B" at reset.

9.4.6 PC (Program Counter)



The program counter indicates the address of the instruction that is being executed.

The initial value at reset is undefined.

Document Number: 002-04604 Rev. *C Page 26 of 81



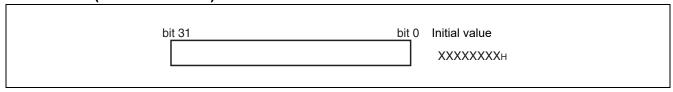
9.4.7 TBR (Table Base Register)

bit 31	bit 0 Initial value
	000FFC00н

The table base register stores the starting address of the vector table used in EIT processing.

The initial value at reset is 000FFC00_H.

9.4.8 RP (Return Pointer)



The return pointer stores the address to return from subroutines.

During execution of a CALL instruction, the PC value is transferred to this RP register.

During execution of a RET instruction, the contents of the RP register are transferred to PC.

The initial value at reset is undefined.

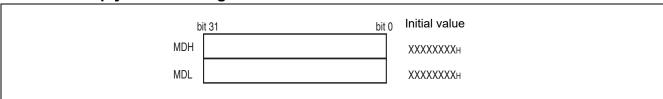
9.4.9 USP (User Stack Pointer)

bit 31	bit 0	Initial value
		XXXXXXXH

When the S flag is "1", the user stack pointer functions as the R15 register.

- The USP register can also be explicitly specified.
 The initial value at reset is undefined.
- This register cannot be used with RETI instructions.

9.4.10 Multiply & Divide Registers



These registers are for multiplication and division, and are each 32 bits in length.

The initial value at reset is undefined.

Document Number: 002-04604 Rev. *C Page 27 of 81



10. Mode Setting

In the FR family, the mode pins (MD2, MD1, MD0) and the mode register (MODR) are used to set the operating mode.

10.1 Mode Pins

The three pins MD2, MD1, MD0 are used to specify the mode vector fetch.

Settings other than shown in the table are prohibited.

Mode Pins ^[1]		[1]	Mode Name	Reset Vector	Remarks	
MD2	MD1	MD0	mode Nume	Access Area	Kemarks	
0	0	0	Internal ROM mode vector	Internal		
0	0	1	External ROM mode vector	External	Not allowed	

^{1.} Always use MD3 with "0".

10.2 Mode Register (MODR)

The data written to the mode register using mode vector fetch is called mode data.

After the mode register (MODR) is set, the device operates according to the operation mode set in this register.

The mode register is set by all reset sources. User programs cannot write data to the mode register.

Rewriting is allowed in the emulator mode. In this case, use an 8-bit length data transfer instruction.

Data cannot be written by the transfer instruction of the 16/32-bit length.

Be sure to set these bits to "00000111_B".

Operation is not guaranteed when any value other than "00000111_B" is set.

Note: The mode data needs to be allocated in $000FFFF8_H$ as byte data. The mode data (00000111_B) must be allocated in bit 31 to bit 24, as the FR family uses the big endian architecture.

Document Number: 002-04604 Rev. *C Page 28 of 81



11. Recommended Setting

11.1 Setting of PLL and Clock Gear

Table 1. Recommended Setting of PLL Division and Clock Gear

Clock Input	Clock Input PLL Multiplied Setting		Clock Gea	r Setting	PLL (vco) Output (X)	Base Clock
[MHz]	DIVM	DIVN	DIVG	MULG	` [MHz] ` `	[MHz]
4	2	20	16	20	160	80
4	2	19	16	20	152	76
4	2	18	16	20	144	72
4	2	17	16	16	136	68
4	2	16	16	16	128	64
4	2	15	16	16	120	60
4	2	14	16	16	112	56
4	2	13	16	12	104	52
4	2	12	16	12	96	48
4	2	11	16	12	88	44
4	4	10	16	24	160	40
4	4	9	16	24	144	36
4	4	8	16	24	128	32
4	4	7	16	24	112	28
4	6	6	16	24	144	24
4	8	5	16	28	160	20
4	10	4	16	32	160	16
4	12	3	16	32	144	12

11.2 Setting of Flash Memory Controller

11.2.1 Setting of Flash Access Timing

For executing programs with a Flash memory, follow the settings below according to the frequency of CPU clock (CLKB). This setting is the most suitable for a high-speed access to the Flash memory.

Table 2. Flash Memory Read Operating

CPU Clock (CLKB)	ATD	ALEH	EQ	WEXH	WTC
To 24 MHz	0	0	0	0	1
To 48 MHz	0	0	1	0	2
To 80 MHz	1	1	3	0	4

Table 3. Flash Memory Write Operating

auto or rision momory mito operating								
CPU Clock (CLKB)	ATD	ALEH	EQ	WEXH	WTC			
To 32 MHz	1	0	1	0	4			
To 48 MHz	1	0	3	0	5			
To 64 MHz	1	1	3	0	6			
To 80 MHz	1	1	3	0	7			

Document Number: 002-04604 Rev. *C Page 29 of 81



11.3 Setting of Clock Modulator

The setting values in the table are defined within the rages of base clock frequency; 32 MHz to 80 MHz. The Flash memory access needs to be configured according to the Fmax. PLL and clock gear need to be configured according to the base clock.

Table 4. Setting of Clock Modulator

Modulation (k)	Internal Parameter (N)	CMPR [hex]	Base Clock [MHz]	Fmin [MHz]	Fmax [MHz]
1	3	026F	80	72.6	89.1
1	3	026F	76	69.1	84.5
1	5	02AE	76	65.3	90.8
2	3	046E	76	65.3	90.8
1	3	026F	72	65.5	79.9
1	5	02AE	72	62	85.8
1	7	02ED	72	58.8	92.7
2	3	046E	72	62	85.8
1	3	026F	68	62	75.3
1	5	02AE	68	58.7	80.9
1	7	02ED	68	55.7	87.3
1	9	032C	68	53	95
2	3	046E	68	58.7	80.9
2	5	04AC	68	53	95
3	3	066D	68	55.7	87.3
4	3	086C	68	53	95
1	3	026F	64	58.5	70.7
1	5	02AE	64	55.3	75.9
1	7	02ED	64	52.5	82
1	9	032C	64	49.9	89.1
2	3	046E	64	55.3	75.9
2	5	04AC	64	49.9	89.1
3	3	066D	64	52.5	82
4	3	086C	64	49.9	89.1
1	3	026F	60	54.9	66.1
1	5	02AE	60	51.9	71
1	7	02ED	60	49.3	76.7
1	9	032C	60	46.9	83.3
2	3	046E	60	51.9	71
2	5	04AC	60	46.9	83.3
3	3	066D	60	49.3	76.7
4	3	086C	60	46.9	83.3
5	3	0A6B	60	44.7	91.3
1	3	026F	56	51.4	61.6
1	5	02AE	56	48.6	66.1
1	7	02ED	56	46.1	71.4
1	9	032C	56	43.8	77.6



Modulation (k)	Internal Parameter (N)	CMPR [hex]	Base Clock [MHz]	Fmin [MHz]	Fmax [MHz]
1	11	036B	56	41.8	84.9
1	13	03AA	56	39.9	93.8
2	3	046E	56	48.6	66.1
2	5	04AC	56	43.8	77.6
2	7	04EA	56	39.9	93.8
3	3	066D	56	46.1	71.4
4	3	086C	56	43.8	77.6
5	3	0A6B	56	41.8	84.9
1	3	026F	52	47.8	57
1	5	02AE	52	45.2	61.2
1	7	02ED	52	42.9	66.1
1	9	032C	52	40.8	71.8
1	11	036B	52	38.8	78.6
1	13	03AA	52	37.1	86.8
2	3	046E	52	45.2	61.2
2	5	04AC	52	40.8	71.8
2	7	04EA	52	37.1	86.8
3	3	066D	52	42.9	66.1
3	5	06AA	52	37.1	86.8
4	3	086C	52	40.8	71.8
5	3	0A6B	52	38.8	78.6
6	3	0C6A	52	37.1	86.8
1	3	026F	48	44.2	52.5
1	5	02AE	48	41.8	56.4
1	7	02ED	48	39.6	60.9
1	9	032C	48	37.7	66.1
1	11	036B	48	35.9	72.3
1	13	03AA	48	34.3	79.9
1	15	03E9	48	32.8	89.1
2	3	046E	48	41.8	56.4
2	5	04AC	48	37.7	66.1
2	7	04EA	48	34.3	79.9
3	3	066D	48	39.6	60.9
3	5	06AA	48	34.3	79.9
4	3	086C	48	37.7	66.1
5	3	0A6B	48	35.9	72.3
6	3	0C6A	48	34.3	79.9
7	3	0E69	48	32.8	89.1
1	3	026F	44	40.6	48.1
1	5	02AE	44	38.4	51.6
1	7	02ED	44	36.4	55.7



Modulation (k)	Internal Parameter (N)	CMPR [hex]	Base Clock [MHz]	Fmin [MHz]	Fmax [MHz]
1	9	032C	44	34.6	60.4
1	11	036B	44	33	66.1
1	13	03AA	44	31.5	73
1	15	03E9	44	30.1	81.4
2	3	046E	44	38.4	51.6
2	5	04AC	44	34.6	60.4
2	7	04EA	44	31.5	73
3	3	066D	44	36.4	55.7
3	5	06AA	44	31.5	73
4	3	086C	44	34.6	60.4
4	5	08A8	44	28.9	92.1
5	3	0A6B	44	33	66.1
6	3	0C6A	44	31.5	73
7	3	0E69	44	30.1	81.4
1	3	026F	40	37	43.6
1	5	02AE	40	34.9	46.8
1	7	02ED	40	33.1	50.5
1	9	032C	40	31.5	54.8
1	11	036B	40	30	59.9
1	13	03AA	40	28.7	66.1
1	15	03E9	40	27.4	73.7
2	3	046E	40	34.9	46.8
2	5	04AC	40	31.5	54.8
2	7	04EA	40	28.7	66.1
2	9	0528	40	26.3	83.3
3	3	066D	40	33.1	50.5
3	5	06AA	40	28.7	66.1
3	7	06E7	40	25.3	95.8
4	3	086C	40	31.5	54.8
4	5	08A8	40	26.3	83.3
5	3	0A6B	40	30	59.9
6	3	0C6A	40	28.7	66.1
7	3	0E69	40	27.4	73.7
8	3	1068	40	26.3	83.3
1	3	026F	36	33.3	39.2
1	5	02AE	36	31.5	42
1	7	02ED	36	29.9	45.3
1	9	032C	36	28.4	49.2
1	11	036B	36	27.1	53.8
1	13	03AA	36	25.8	59.3
1	15	03E9	36	24.7	66.1



Modulation (k)	Internal Parameter (N)	CMPR [hex]	Base Clock [MHz]	Fmin [MHz]	Fmax [MHz]
2	3	046E	36	31.5	42
2	5	04AC	36	28.4	49.2
2	7	04EA	36	25.8	59.3
2	9	0528	36	23.7	74.7
3	3	066D	36	29.9	45.3
3	5	06AA	36	25.8	59.3
3	7	06E7	36	22.8	85.8
4	3	086C	36	28.4	49.2
4	5	08A8	36	23.7	74.7
5	3	0A6B	36	27.1	53.8
6	3	0C6A	36	25.8	59.3
7	3	0E69	36	24.7	66.1
8	3	1068	36	23.7	74.7
9	3	1267	36	22.8	85.8
1	3	026F	32	29.7	34.7
1	5	02AE	32	28	37.3
1	7	02ED	32	26.6	40.2
1	9	032C	32	25.3	43.6
1	11	036B	32	24.1	47.7
1	13	03AA	32	23	52.5
1	15	03E9	32	22	58.6
2	3	046E	32	28	37.3
2	5	04AC	32	25.3	43.6
2	7	04EA	32	23	52.5
2	9	0528	32	21.1	66.1
2	11	0566	32	19.5	89.1
3	3	066D	32	26.6	40.2
3	5	06AA	32	23	52.5
3	7	06E7	32	20.3	75.9
4	3	086C	32	25.3	43.6
4	5	08A8	32	21.1	66.1
5	3	0A6B	32	24.1	47.7
5	5	0AA6	32	19.5	89.1
6	3	0C6A	32	23	52.5
7	3	0E69	32	22	58.6
8	3	1068	32	21.1	66.1
9	3	1267	32	20.3	75.9
10	3	1466	32	19.5	89.1
	· ·			· · · · · · · · · · · · · · · · · · ·	



12. Memory Space

12.1 Memory space

The FR family has 4 Gbytes of logical address space (2³² addresses) available to the CPU by linear access.

■ Direct addressing area

The following address space area is used for I/O.

This area is called direct addressing area, and the address of an operand can be specified directly in an instruction.

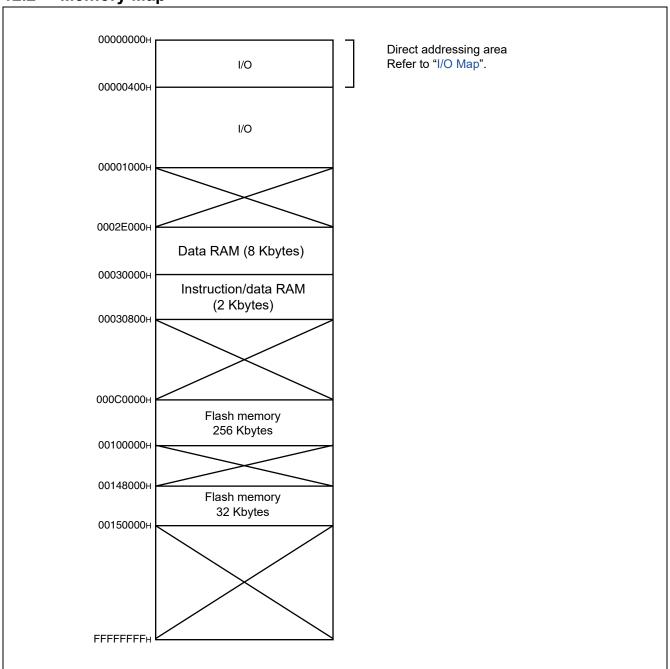
The size of directly addressable area depends on the length of the data to be accessed as shown below.

Byte data access: $000_{\rm H}$ to $0{\rm FF_H}$ Half word access: $000_{\rm H}$ to $1{\rm FF_H}$ Word data access: $000_{\rm H}$ to $3{\rm FF_H}$

Document Number: 002-04604 Rev. *C Page 34 of 81



12.2 Memory Map





12.3 Flash Memory Sector Configuration

addr	CY91F463NC
0014:FFFFн 0014:E000н	SA7(8 Kbytes)
0014:DFFFн 0014:С000н	SA6(8 Kbytes)
0014:BFFFн 0014:A000н	SA5(8 Kbytes)
0014:9FFFн 0014:8000н	SA4(8 Kbytes)
0014:7FFFн 0014:6000н	SA3(8 Kbytes)
0014:5FFFн 0014:4000н	SA2(8 Kbytes)
0014:3FFFн	SA1(8 Kbytes)
0014:2000н 0014:1FFFн	SA0(8 Kbytes)
0014:0000н 0013:FFFFн	SA23(64 Kbytes)
0013:0000н 0012:FFFFн	SA22(64 Kbytes)
0012:0000н 0011:FFFFн	SA21(64 Kbytes)
0011:0000н 0010:FFFFн	, ,
0010:0000н 000F:FFFFн	SA20(64 Kbytes)
000F:0000н 000E:FFFFн	SA19(64 Kbytes)
000E:0000н 000D:FFFFн	SA18(64 Kbytes)
000D:0000н	SA17(64 Kbytes)
000С:FFFFн 000С:0000н	SA16(64 Kbytes)
000B:FFFFн 000B:0000н	SA15(64 Kbytes)
000A:FFFFн 000A:0000н	SA14(64 Kbytes)
0009:FFFFн 0009:0000н	SA13(64 Kbytes)
0008:FFFFн 0008:0000н	SA12(64 Kbytes)
0007:FFFFн 0007:0000н	SA11(64 Kbytes)
0006:FFFFн 0006:0000н	SA10(64 Kbytes)
0005:FFFFн 0005:0000н	SA9(64 Kbytes)
0003.0000н 0004:FFFFн 0004:0000н	SA8(64 Kbytes)
	addr+0 addr+1 addr+2 addr+3
16-bit write mode 32-bit read mode	dat[31:16] dat[15:0] dat[31:0]

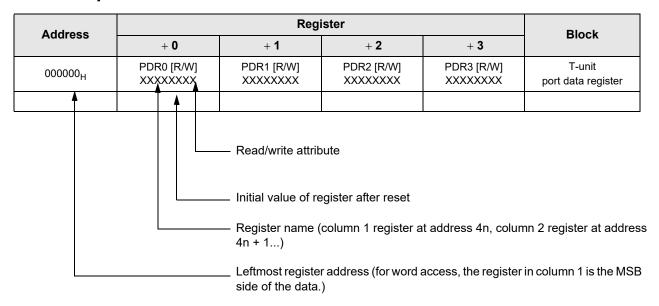
The shaded area is unusable.

Note: CY91F463NC has a different sector map for the flash memory to that of CY91F463NA. The sector map showed above is suited for CY91F463NC, not for CY91F463NA.

Document Number: 002-04604 Rev. *C Page 36 of 81



13. I/O Map



Note: Initial values of register bits are represented as follows:

- " 1 ": Initial value " 1 "
- " 0 ": Initial value " 0 "
- " X ": Initial value " undefined "
- " ": No physical register at this location

Access is prohibited to areas where the data access attributes are undefined.



Address		Register					
Address	+0	+1	+2	+3	Block		
000000 _H to 000008 _H							
00000C _H	Rese	erved	PDR14 [R/W] XXXX	PDR15 [R/W] XXXX			
000010 _H	Reserved	PDR17 [R/W] XXXXXXXX	Rese	erved	R-bus		
000014 _H	PDR20 [R/W] -XXX-XXX	PDR21 [R/W] -XXX-XXX	PDR22 [R/W] XXXX	Reserved	Port Data Register		
000018 _H	PDR24 [R/W] XXXXXXXX		Reserved				
00001C _H	Reserved	PDR29 [R/W] XXXXXXXX	Rese	erved			
000020 _H		Rese	erved				
000024 _H to 00002C _H		Rese	erved		Reserved		
000030 _H	EIRR0 [R/W] 00000000	ENIR0 [R/W] 00000000	ELVR0 00000000		External interrupt 0 to 7		
000034 _H	EIRR1 [R/W] 00000000	ENIR1 [R/W] 00000000	ELVR1 [R/W] 00000000 00000000		External interrupt 12, 13		
000038 _H	DICR [R/W]	HRCL [R/W] 0 11111	Rese	erved	DLYI/I-unit		
00003C _H		Rese	erved		Reserved		
000040 _H	SCR00 [R/W, W] 00000000	SMR00 [R/W, W] 00000000	SSR00 [R/W, R] 00001000	RDR00/TDR00 [R/W] 00000000	LIN-USART0		
000044 _H	ESCR00 [R/W] 00000X00	ECCR00 [R/W, R, W] 000000XX	Rese	erved	LIN-USARTU		
000048 _H	SCR01 [R/W, W] 00000000	SMR01 [R/W, W] 00000000	SSR01 [R/W, R] 00001000	RDR01/TDR01 [R/W] 00000000	LINLUCADTA		
00004C _H	ESCR01 [R/W] 00000X00	ECCR01 [R/W, R, W] 000000XX	Rese	erved	LIN-USART1		
000050 _H	SCR02 [R/W, W] 00000000	SMR02 [R/W, W] 00000000	SSR02 [R/W, R] 00001000	RDR02/TDR02 [R/W] 00000000	LINLIGATO		
000054 _H	ESCR02 [R/W] 00000X00	ECCR02 [R/W, R, W] 000000XX	Reserved		LIN-USART2		
000058 _H	SCR03 [R/W, W] 00000000	SMR03 [R/W, W] 00000000	SSR03 [R/W, R] 00001000	RDR03/TDR03 [R/W] 00000000	LINLLICADTO		
00005C _H	ESCR03 [R/W] 00000X00	ECCR03 [R/W, R, W] 000000XX	Rese	erved	LIN-USART3		



A d d		Block			
Address	+0				
000060 _H to 00007C _H		Rese	erved		Reserved
000080 _H	BGR100 [R/W] 00000000	BGR000 [R/W] 00000000	BGR101 [R/W] 00000000	BGR001 [R/W] 00000000	
000084 _H	BGR102 [R/W] 00000000	BGR002 [R/W] 00000000	BGR103 [R/W] 00000000	BGR003 [R/W] 00000000	Baud rate Generator LIN-USART0 to 3
000088 _H , 00008C _H		Rese	erved		EIIV OO/II(TO IO (
000090 _H to 0000FC _H		Rese	erved		Reserved
000100 _H	GCN10 00110010		Reserved	GCN20 [R/W] 0000	PPG Control 0 to 3
000104 _H	GCN11 00110010		Reserved	GCN21 [R/W] 0000	PPG Control 4 to 7
000108 _H		Rese	erved		Reserved
000110 _H	PTMR 11111111			00 [W] XXXXXXX	PDC 6
000114 _H	PDUT(XXXXXXXX		PCNH00 [R/W] 0000000 -	PCNL00 [R/W] 000000 - 0	- PPG 0
000118 _H	PTMR01 [R]				DDC 4
00011C _H	PDUT(XXXXXXXX		PCNH01 [R/W] 0000000 -	PCNL01 [R/W] 000000 - 0	- PPG 1
000120 _H	PTMR02 [R] 11111111 11111111		PCSR02 [W] XXXXXXXX XXXXXXX		- PPG 2
000124 _H	PDUT(XXXXXXXX		PCNH02 [R/W] 0000000 -	PCNL02 [R/W] 000000 - 0	- PPG 2
000128 _H	PTMR 11111111	= =		03 [W] XXXXXXXX	DDC 0
00012C _H	PDUT(XXXXXXXX		PCNH03 [R/W] 0000000 -	PCNL03 [R/W] 000000 - 0	- PPG 3
000130 _H	PTMR 11111111			04 [W] XXXXXXXX	- PPG 4
000134 _H	PDUT(XXXXXXXX		PCNH04 [R/W] 0000000 -	PCNL04 [R/W] 000000 - 0	7 7764
000138 _H	PTMR 11111111			05 [W] XXXXXXXX	PPG 5
00013C _H	PDUT(XXXXXXXX	• •	PCNH05 [R/W] 0000000 -	PCNL05 [R/W] 000000 - 0	FFG 5
000140 _H	PTMR06 [R] PCSR06 [W] 11111111 XXXXXXXX XXXXXXXX		PPG 6		
000144 _H	PDUT(XXXXXXXX		PCNH06 [R/W] 0000000 -	PCNL06 [R/W] 000000 - 0	7760
000148 _H	PTMR 11111111	• •		07 [W] XXXXXXX	DDC 7
00014C _H	PDUT(XXXXXXXX		PCNH07 [R/W] 0000000 -	PCNL07 [R/W] 000000 - 0	- PPG 7



Adduses		Block			
Address	+0				
000150 _H to 00017C _H		Rese	erved		Reserved
000180 _H	Reserved	ICS01 [R/W] 00000000	Reserved	ICS23 [R/W] 00000000	la muit
000184 _H	IPCP XXXXXXXX	0 [R] XXXXXXXX		1 [R] XXXXXXXX	Input Capture 0 to 3
000188 _H	IPCP XXXXXXXX	2 [R] XXXXXXXX		3 [R] XXXXXXXX	
00018C _H		[R/W] 0000 00		3 [R/W] 0000 00	
000190 _H	OCCP(XXXXXXXX	(R/W) XXXXXXXX		1 [R/W] XXXXXXXX	Output Compare 0 to 3
000194 _H	OCCP2 XXXXXXXX	2 [R/W] XXXXXXXX		3 [R/W] XXXXXXXX	3 0 10 0
000198 _H , 00019C _H		Rese	erved		Reserved
0001A0 _H		Reserved		ADERL [R/W] 00000000	
0001A4 _H	ADCS1 [R/W] 00000000	ADCS0 [R/W] 00000000	ADCR1 [R] 000000XX	ADCR0 [R] XXXXXXXX	A/D Converter
0001A8 _H	ADCT1 [R/W] 00010000	ADCT0 [R/W] 00101100	ADSCH [R/W] 00000	ADECH [R/W] 00000	
0001AC _H		Rese	erved		Reserved
0001B0 _H	TMRLF XXXXXXXX	RO [W] XXXXXXXX	TMR0 [R] XXXXXXXX XXXXXXX		Daland Timer 0
0001B4 _H	Rese	erved	TMCSRH0 [R/W] 00000	TMCSRL0 [R/W] 0 - 000000	Reload Timer 0 (PPG0, PPG1)
0001B8 _H	TMRLF XXXXXXXX	R1 [W] XXXXXXXX		1 [R] XXXXXXXX	Dala ad Timon A
0001BC _H	Rese	erved	TMCSRH1 [R/W] 00000	TMCSRL1 [R/W] 0 - 000000	Reload Timer 1 (PPG2, PPG3)
0001C0 _H		R2 [W] XXXXXXXX		2 [R] XXXXXXXX	Daland Timon 2
0001C4 _H	Rese	erved	TMCSRH2 [R/W] 00000	TMCSRL2 [R/W] 0 - 000000	Reload Timer 2 (PPG4, PPG5)
0001C8 _H	TMRLR3 [W] XXXXXXXX XXXXXXX			3 [R] XXXXXXXX	Dalas IT
0001CC _H	Rese	erved	TMCSRH3 [R/W] 00000	TMCSRL3 [R/W] 0 - 000000	Reload Timer 3 (PPG6, PPG7)
0001D0 _H to 0001E7 _H		Rese	erved		Reserved



Address		Reg	ister		Dlack	
Address	+0	+1	+2	+3	Block	
0001E8 _H	TMRLF XXXXXXXX	7 [R] XXXXXXXX				
0001EC _H	Rese	rved	TMCSRH7 [R/W] 00000	TMCSRL7 [R/W] 0 - 000000	Reload Timer 7 (A/D converter)	
0001F0 _H	TCDT0 XXXXXXXX		Reserved	TCCS0 [R/W] 00000000	Free-run Timer 0 (ICU0, ICU1)	
0001F4 _H	TCDT1 XXXXXXXX		Reserved	TCCS1 [R/W] 00000000	Free-run Timer 1 (ICU2, ICU3)	
0001F8 _H	TCDT2 XXXXXXXX		Reserved	TCCS2 [R/W] 00000000	Free-run Timer 2 (OCU0, OCU1)	
0001FC _H	TCDT3 XXXXXXXX		Reserved	TCCS3 [R/W] 00000000	Free-run Timer 3 (OCU2, OCU3)	
000200 _H		DMACA0 00000000 0000XXXX X	[R/W] *			
000204 _H) [R/W] XXXXXXX XXXXXXXX			
000208 _H			[R/W] * XXXXXXXX XXXXXXXX			
00020C _H			1 [R/W] XXXXXXX XXXXXXXX			
000210 _H		DMACA2 00000000 0000XXXX X	[R/W] *			
000214 _H			2 [R/W] XXXXXXX XXXXXXXX			
000218 _H			[R/W] *		DMAC	
00021C _H			B [R/W] XXXXXXX XXXXXXXX			
000220 _H			[R/W] *			
000224 _H			4 [R/W] XXXXXXX XXXXXXXX			
000228 _H to 00023C _H		Reserved				
000240 _H	DMACR [R/W] 0 0000		Reserved			
000244 _H to 0002FC _H	Reserved				Reserved	
000300 _H	UDRC1 [W] 00000000	UDRC0 [W] 00000000	UDCR1 [R] 00000000	UDCR0 [R] 00000000		
000304 _H	UDCCH0 [R/W] 00000000	UDCCL0 [R/W] 00001000	Reserved	UDCS0 [R/W] 00000000	Up/Down Counter 0, 1	
000308 _H	UDCCH1 [R/W] 00000000	UDCCL1 [R/W] 00001000	Reserved	UDCS1 [R/W] 00000000		



Address		Plack					
Address	+0	+1	+2	+3	Block		
00030C _H to 000364 _H		Reserved					
000368 _H	IBCR2 [R/W] 00000000	IBSR2 [R] 00000000	ITBAH2 [R/W] 00	ITBAL2 [R/W] 00000000			
00036C _H	ITMKH2 [R/W] 00 11	ITMKL2 [R/W] 11111111	ISMK2 [R/W] 01111111	ISBA2 [R/W] - 0000000	I ² C 2		
000370 _H	Reserved	IDAR2 [R/W] 00000000	ICCR2 [R/W] - 0011111	Reserved			
000374 _H	IBCR3 [R/W] 00000000	IBSR3 [R] 00000000	ITBAH3 [R/W] 00	ITBAL3 [R/W] 00000000			
000378 _H	ITMKH3 [R/W] 00 11	ITMKL3 [R/W] 11111111	ISMK3 [R/W] 01111111	ISBA3 [R/W] - 0000000	I ² C 3		
00037C _H	Reserved	IDAR3 [R/W] 00000000	ICCR3 [R/W] - 0011111	Reserved			
000380 _H to 00038C _H		Reserved					
000390 _H		1S [R] 01001111	Res	erved	ROM Select Register		
000394 _H to 0003EC _H		Reserved					
0003F0 _H		BSD0 XXXXXXXX XXXXXXXX		(
0003F4 _H		BSD1 XXXXXXXX XXXXXXXX	• •	(Bit Search Module		
0003F8 _H		BSDC XXXXXXXX XXXXXXXX		(
0003FC _H		BSRR XXXXXXXX XXXXXXXX		(
000400 _H to 00043C _H		Rese	erved		Reserved		
000440 _H	ICR00 [R/W] 11111	ICR01 [R/W] 11111	ICR02 [R/W] 11111	ICR03 [R/W] 11111			
000444 _H	ICR04[R/W] 11111	ICR05 [R/W] 11111	ICR06 [R/W] 11111	ICR07 [R/W] 11111			
000448 _H	ICR08 [R/W] 11111	ICR09 [R/W] 11111	ICR10[R/W] 11111	ICR11 [R/W] 11111	Interrupt Control Unit		
00044C _H	ICR12 [R/W] 11111	ICR13[R/W] 11111	ICR14[R/W] 11111	ICR15[R/W] 11111			
000450 _H	ICR16[R/W] 11111	ICR17[R/W] 11111	ICR18 [R/W] 11111	ICR19 [R/W] 11111			



A ddwggg		Pleak			
Address	+0	+1	+2	+3	Block
000454 _H	ICR20 [R/W] 11111	ICR21 [R/W] 11111	ICR22 [R/W] 11111	ICR23 [R/W] 11111	
000458 _H	ICR24[R/W] 11111	ICR25[R/W] 11111	ICR26[R/W] 11111	ICR27[R/W] 11111	
00045C _H	ICR28[R/W] 11111	ICR29 [R/W] 11111	ICR30[R/W] 11111	ICR31[R/W] 11111	
000460 _H	ICR32[R/W] 11111	ICR33[R/W] 11111	ICR34[R/W] 11111	ICR35[R/W] 11111	
000464 _H	ICR36[R/W] 11111	ICR37[R/W] 11111	ICR38 [R/W] 11111	ICR39 [R/W] 11111	
000468 _H	ICR40[R/W] 11111	ICR41[R/W] 11111	ICR42 [R/W] 11111	ICR43 [R/W] 11111	Interrupt Control Unit
00046C _H	ICR44[R/W] 11111	ICR45[R/W] 11111	ICR46[R/W] 11111	ICR47[R/W] 11111	
000470 _H	ICR48 [R/W] 11111	ICR49 [R/W] 11111	ICR50 [R/W] 11111	ICR51 [R/W] 11111	
000474 _H	ICR52[R/W] 11111	ICR53[R/W] 11111	ICR54[R/W] 11111	ICR55[R/W] 11111	
000478 _H	ICR56 [R/W] 11111	ICR57[R/W] 11111	ICR58 [R/W] 11111	ICR59 [R/W] 11111	_
00047C _H	ICR60[R/W] 11111	ICR61 [R/W] 11111	ICR62 [R/W] 11111	ICR63 [R/W] 11111	
000480 _H	RSRR [R/W] 10000000	STCR [R/W] 001100-1	TBCR [R/W] 00XXXX00	CTBR [W] XXXXXXXX	
000484 _H	CLKR [R/W]	WPR [W] XXXXXXX	DIVR0 [R/W] 00000011	DIVR1 [R/W] 00000000	Clock Control Unit
000488 _H		Res	erved		Reserved
00048C _H	PLLDIVM [R/W] 0000	PLLDIVN [R/W] 000000	PLLDIVG [R/W] 0000	PLLMULG [R/W] 00000000	BU 01 1 0 11 7
000490 _H	PLLCTRL [R/W]		Reserved		PLL Clock Gear Unit
000494 _H		Res	erved		Reserved
000498 _H	PORTEN [R/W] 00		Reserved		Port Input Enable Control
00049C _H		Res	erved		Reserved
0004A0 _H	Reserved	WTCER [R/W] 00		R [R/W] 000 - 00 - 0	
0004A4 _H	Reserved	X	Real Time Clock (Watch Timer)		
0004A8 _H	WTHR [R/W] 00000	WTMR [R/W] 000000	WTSR [R/W] 000000	Reserved	
0004AC _H	Rese	erved	CSCFG [R/W] 0X000000	CMCFG [R/W] 00000000	Clock Monitor
0004B0 _H , 0004B4 _H		Res	erved		Reserved



Address			Block			
Address	+0	+1	+2	+3	- BIOCK	
0004B8 _H	CMPR [R/W] 000010 11111101		Reserved	CMCR [R/W] - 001 00	Clock	
0004BC _H		[R/W] 1 0000		2 [R/W] 000000	Modulator	
0004C0 _H	CANPRE [R/W] 00000000	CANCKD [R/W] 00	Res	erved	CAN Clock Control	
0004C4 _H	Reserved	LVDET [R/W] 00000 - 00	HWWDE [R/W] 00	HWWD [R/W, W] 00011000	Low-voltage Detection	
0004C8 _H	OSCRH [R/W] 000 001	OSCRL [R/W] 000	Reso	erved	Main-Oscillation	
0004CC _H		Res	erved		Stabilization Timer	
0004D0 _H to 0007F8 _H		Res	Reserved			
0007FC _H	Reserved	MODR [W] XXXXXXXX	Reso	Mode Register		
000800 _H to 000CFC _H		Reserved				
000D00 _H to 000D08 _H		Res	erved			
000D0C _H	Rese	erved	PDRD14 [R] XXXX	PDRD15 [R]		
000D10 _H	Reserved	PDRD17 [R] XXXXXXXX	Res	erved	R-bus Port Data	
000D14 _H	PDRD20 [R] - XXX- XXX	PDRD21 [R] - XXX- XXX	PDRD22 [R] XXXX	Reserved	Direct Read Register	
000D18 _H	PDRD24 [R] XXXXXXXX		Reserved Reserved			
000D1C _H	Reserved	PDRD29 [R] XXXXXXXX				
000D20 _H	Reserved					
000D24 _H to 000D3C _H	Reserved				Reserved	



A 1.1		511			
Address	+0	+1	+2	+3	Block
000D40 _H to 000D48 _H					
000D4C _H	Reso				
000D50 _H	Reserved	DDR17 [R/W] 00000000	Rese	erved	R-bus Port Direction
000D54 _H	DDR20 [R/W] -000- 000	DDR21 [R/W] -000- 000	DDR22 [R/W] 0000	Reserved	Register
000D58 _H	DDR24 [R/W] 00000000		Reserved		
000D5C _H	Reserved	DDR29 [R/W] 00000000	Rese	erved	
000D60 _H		Rese	rved		
000D64 _H to 000D7C _H		Rese	rved		Reserved
000D80 _H to 000D88 _H		Rese	rved		
000D8C _H	Reso	erved	PFR14 [R/W] 0000	PFR15 [R/W] 0000	
000D90 _H	Reserved	PFR17 [R/W] 00000000	Rese	erved	R-bus Port Function
000D94 _H	PFR20 [R/W] -000- 000	PFR21 [R/W] -000- 000	PFR22 [R/W] 0000	Reserved	Register
000D98 _H	PFR24 [R/W] 00000000		Reserved		
000D9C _H	Reserved	PFR29 [R/W] 00000000	Rese	erved	
000DA0 _H		Rese	rved		
000DA4 _H to 000DBC _H		Rese	rved		Reserved
000DC0 _H to 000DC8 _H		Rese	rved		R-bus Extension Port
000DCC _H	Rese	erved	EPFR14 [R/W] 0000	EPFR15 [R/W] 0000	Function Register
000DD0 _H					
000DD4 _H	EPFR20 [R/W] - 000- 000	R-bus Extension Port			
000DD8 _H		Rese	rved		Function Register
000DDC _H					
000DE0 _H		Rese	rved		
000DE4 _H to 000DFC _H		Rese	erved		Reserved



A 1.1		BL. I				
Address -	+0	+1	+2	+3	Block	
000E00 _H to 000E08 _H						
000E0C _H	Rese	erved	PODR14 [R/W] 0000	PODR15 [R/W] 0000		
000E10 _H	Reserved	PODR17 [R/W] 00000000	Rese	erved	R-bus Port Output	
000E14 _H	PODR20 [R/W] - 000- 000	PODR21 [R/W] - 000- 000	PODR22 [R/W] 0000	Reserved	Drive Select Register	
000E18 _H	PODR24 [R/W] 00000000		Reserved			
000E1C _H	Reserved	PODR29 [R/W] 00000000	Rese	erved		
000E20 _H		Rese	erved			
000E24 _H to 000E3C _H		Rese	erved		Reserved	
000E40 _H to 000E48 _H		Rese	erved			
000E4C _H	Rese	erved	PILR14 [R/W] 0000	PILR15 [R/W] 0000		
000E50 _H	Reserved	PILR17 [R/W] 00000000	Rese	erved	R-bus Pin	
000E54 _H	PILR20 [R/W] - 000- 000	PILR21 [R/W] -000- 000	PILR22 [R/W] 0000	Reserved	Input Level Select Register	
000E58 _H	PILR24 [R/W] 00000000		Reserved			
000E5C _H	Reserved	PILR29 [R/W] 00000000	Rese	erved		
000E60 _H		Rese	erved			
000E64 _H to 000E7C _H		Rese	erved		Reserved	
000E80 _H to 000E88 _H		Rese	erved			
000E8C _H	Rese	erved	EPILR14 [R/W]	EPILR15 [R/W]		
000E90 _H	Reserved	EPII R17 (R/M)				
000E94 _H	EPILR20 [R/W] - 000- 000	EPILR21 [R/W] - 000- 000	EPILR22 [R/W] 0000	Reserved	Level Select Register	
000E98 _H	EPILR24 [R/W] 00000000	Reserved				
000E9C _H , 000EA0 _H	Reserved					



A d due e e		Reg	ister		Disak	
Address -	+0	+1	+2	+3	Block	
000EA4 _H to 000EBC _H		Rese	erved		Reserved	
000EC0 _H to 000EC8 _H		Rese	erved			
000ECC _H	Rese	erved	PPER14 [R/W] 0000	PPER15 [R/W] 0000		
000ED0 _H	Reserved	PPER17 [R/W] 00000000	Reso	erved	R-bus Port	
000ED4 _H	PPER20 [R/W] -000- 000	PPER21 [R/W] -000- 000	PPER22 [R/W] 0000	Reserved	Pull-up/down Enable Register	
000ED8 _H	PPER24 [R/W] 00000000		Reserved			
000EDC _H	Reserved	PPER29 [R/W] 00000000	Reso	erved		
000EE0 _H		Rese	erved			
000EE4 _H to 000EFC _H		Rese	erved		Reserved	
000F00 _H to 000F08 _H		Rese	erved		R-bus Port Pull-up/down Control- Register	
000F0C _H	Rese	erved	PPCR14 [R/W] 1111	PPCR15 [R/W] 1111		
000F10 _H	Reserved	PPCR17 [R/W] 11111111	Res	erved		
000F14 _H	PPCR20 [R/W] -111-111	PPCR21 [R/W] -111-111	PPCR22 [R/W] 1111	Reserved	R-bus Port Pull-up/down Control	
000F18 _H	PPCR24 [R/W] 11111111		Reserved			
000F1C _H	Reserved	PPCR29 [R/W] 11111111				
000F20 _H	Reserved					
000F24 _H to 000F3C _H	Reserved				Reserved	



Address		Block				
Address	+0	+1	+2	+3	BIOCK	
001000 _H						
001004 _H		DMADA0 [R/W] XXXXXXXX XXXXXXXX XXXXXXXX				
001008 _H		DMASA XXXXXXXX XXXXXXX				
00100C _H		DMADA XXXXXXXX XXXXXXXX				
001010 _H		DMASA XXXXXXXX XXXXXXXX			- DMAC	
001014 _H		DMADA XXXXXXXX XXXXXXXX	• •		DIWAG	
001018 _H		DMASA XXXXXXXX XXXXXXXX				
00101C _H		DMADA XXXXXXXX XXXXXXXX				
001020 _H		DMASA XXXXXXXX XXXXXXXX				
001024 _H		DMADA XXXXXXXX XXXXXXXX				
001028 _H to 006FFC _H		Reserved				
007000 _H	FMCS [R/W] 01101000	FMCR [R/W] 0000	FCHCI	R [R/W] 10000011		
007004 _H		[R/W] 01011101	FMWT2 [R/W] - 101	FMPS [R/W] 000	Flash Memory/ I-Cache Control Register	
007008 _H		FMA 00000	C[R] 00000000 00000000		, , ,	
00700C _H		FCHA0			I-Cache Non-cacheable area	
007010 _H		setting Register				
007014 _H to		Reserved				
00AFFC _H		1,6361760				
00B000 _H to 00BFFC _H		BI-ROM size is 4 Kbytes	: : 00B000 _H to 00BFFF _H		BI-ROM 4 Kbytes	
00C000 _H to 00C3FC _H		Rese	rved		Reserved	



Address		Reg	gister		Diagk
Address	+0	+1	+2	+3	Block
00C400 _H	CTRLR4 00000000			4 [R/W] 00000000	
00C404 _H	ERRCN 00000000			[R/W] 00000001	CAN 4 Control
00C408 _H	INTR- 00000000			4 [R/W] X0000000	Register
00C40C _H	BRPE4 00000000		Rese	erved	
00C410 _H	IF1CREC 00000000			K4 [R/W] 00000000	
00C414 _H	IF1MSK2 11111111			IF1MSK14 [R/W] 11111111 11111111	
00C418 _H	IF1ARB2 00000000			IF1ARB14 [R/W] 00000000 00000000	
00C41C _H	IF1MCTF 00000000		Rese	Reserved	
00C420 _H	IF1DTA1 00000000			IF1DTA24 [R/W] 00000000 00000000	
00C424 _H	IF1DTB1 00000000			24 [R/W] 00000000	
00C428 _H , 00C42C _H		Res	served		
00C430 _H	IF1DTA2 00000000			14 [R/W] 00000000	
00C434 _H	IF1DTB2 00000000			14 [R/W] 00000000	CAN 4 IF1 Register
00C438 _H , 00C43C _H		Res	served		



Addass		Re	gister		Black		
Address	+0	+1	+2	+3	Block		
00C440 _H	IF2CREC 00000000			MSK4 [R/W] 00 00000000			
00C444 _H	IF2MSK2 11111111		SK14 [R/W] 11 11111111				
00C448 _H	IF2ARB2 00000000			RB14 [R/W] 00 00000000			
00C44C _H	IF2MCTF 00000000		R	eserved			
00C450 _H	IF2DTA1 00000000			TA24 [R/W] 00 00000000	CAN 4		
00C454 _H	IF2DTB1 00000000			TB24 [R/W] 00 00000000	CAN 4 IF2 Register		
00C458 _H , 00C45C _H		Res	served				
00C460 _H	IF2DTA2 00000000			IF2DTA14 [R/W] 00000000 00000000			
00C464 _H	IF2DTB2 00000000			IF2DTB14 [R/W] 00000000 00000000			
00C468 _H to 00C47C _H		Res	served				
00C480 _H	TREQR 00000000			EQR14 [R] 00 00000000			
00C484 _H	TREQR 00000000			EQR34 [R] 00 00000000			
00C488 _H	TREQR 00000000			EQR54 [R] 00 00000000	CAN 4		
00C48C _H	TREQR 00000000			TREQR74 [R] 00000000 00000000			
00C490 _H	NEWD1 00000000	NDT14 [R] 00 00000000					
00C494 _H	NEWD7 00000000			NDT34 [R] 00 00000000	_		



Address	Register					
Address	+0	+1	+2	+3	Block	
00C498 _H	NEWDT 00000000			DT54 [R]) 00000000		
00C49C _H	NEWDT 00000000			DT74 [R] D 00000000		
00C4A0 _H	INTPND 00000000			ND14 [R] 0 00000000		
00C4A4 _H	INTPND 00000000			ND34 [R] 0 00000000		
00C4A8 _H	INTPND 00000000			ND54 [R] 0 00000000		
00C4AC _H	INTPND 00000000			ND74 [R] 0 00000000	CAN 4 Status Flags	
00C4B0 _H	MSGVAL 00000000			/AL14 [R] 0 00000000		
00C4B4 _H	MSGVAL 00000000			MSGVAL34 [R] 00000000 00000000		
00C4B8 _H	MSGVAL 00000000		MSGV 00000000			
00C4BC _H	MSGVAL 00000000		MSGV 00000000			
00C4C0 _H to 00C4FC _H		Rese	erved			
00C500 _H	CTRLR5 00000000			R5 [R/W] 0 00000000		
00C504 _H	ERRCN 00000000			5 [R/W] 1 00000001	CAN 5	
00C508 _H	INTR5 00000000			R5 [R/W]) X0000000	Control Register	
00C50C _H	BRPE5 00000000		Res	served		
00C510 _H	IF1CREQ 00000000			SK5 [R/W] 0 00000000		
00C514 _H	IF1MSK2 11111111			K15 [R/W] 1 11111111		
00C518 _H	JE1MCTR5 [R/W]		IF1ARB15 [R/W] 00000000 00000000		CAN 5 IF1 Register	
00C51C _H			Reserved			
00C520 _H	IF1DTA15 00000000		IF1DT/ 00000000			



Address	Register							
Address	+0	+1	+2 +3		Block			
00C524 _H		IF1DTB15 [R/W] IF1DTB25 [R/W] 00000000 00000000 00000000 00000000						
00C528 _H , 00C52C _H								
00C530 _H	IF1DTA25 [R/W] 00000000 00000000			A15 [R/W]) 00000000	CAN 5 IF1 Register			
00C534 _H	IF1DTB2 00000000			B15 [R/W] 0 00000000				
00C538 _H , 00C53C _H		Rese	erved					
00C540 _H	IF2CREQ 00000000			SK5 [R/W] 0 00000000				
00C544 _H	IF2MSK2 11111111		IF2MSI 11111111					
00C548 _H	IF2ARB2 00000000			IF2ARB15 [R/W] 00000000 00000000				
00C54C _H	IF2MCTR 00000000		Res	served	7			
00C550 _H	IF2DTA1 00000000			A25 [R/W] 0 00000000	CAN 5			
00C554 _H	IF2DTB1 00000000			325 [R/W] 0 00000000	IF2 Register			
00C558 _H , 00C55C _H		Rese	erved					
00C560 _H	IF2DTA2 00000000			IF2DTA15 [R/W] 00000000 00000000				
00C564 _H	IF2DTB2 00000000		315 [R/W] 0 00000000					
00C568 _H to 00C57C _H		Rese	erved					



Adduses	Register					
Address	+0	+1	+2	+3	Block	
00C580 _H	TREQR 00000000			QR15 [R] 00 00000000		
00C584 _H	TREQR 00000000			EQR35 [R] 00 00000000		
00C588 _H	TREQR 00000000			EQR55 [R] 00 00000000		
00C58C _H	TREQR 00000000			EQR75 [R] 00 00000000		
00C590 _H	NEWDT 00000000			VDT15 [R] 00 00000000		
00C594 _H	NEWDT 00000000			VDT35 [R] 00 00000000		
00C598 _H	NEWDT 00000000	• •		NEWDT55 [R] 00000000 00000000		
00C59C _H	NEWDT 00000000	• •	NEV 0000000	CAN 5 Status Flags		
00C5A0 _H	INTPND 00000000		INTF 0000000			
00C5A4 _H	INTPND 00000000		INTF 0000000			
00C5A8 _H	INTPND 00000000			PND55 [R] 00 00000000		
00C5AC _H	INTPND 00000000	• •		PND75 [R] 00 00000000		
00C5B0 _H	MSGVAI 00000000			SVAL15 [R] 00 00000000		
00C5B4 _H	MSGVAI 00000000			SVAL35 [R] 00 00000000		
00C5B8 _H	MSGVAI 00000000		MSG 0000000			
00C5BC _H	MSGVAI 00000000			SVAL75 [R] 00 00000000		
00C5C0 _H to 00EFFC _H		Rese	erved			



Address		Reg	ister		Block
Address	+0	+1	+2	+3	DIOCK
00F000 _H			[R/W] 11111100 00000000		
00F004 _H			[R/W] 00000000 10 0000		
00F008 _H		00000000 000000000	[R] 00000000 00000000		
00F00C _H		00000000 00000000	C [R] 00000000 00000000		
00F010 _H			[R/W] 00000000 00000000		
00F014 _H to 00F01C _H		Res	erved		EDSU / MPU
00F020 _H			[R/W] 0 00000000 00000000		
00F024 _H			[R/W] 0 00000000 00000000		
00F028 _H			[R/W] 0 00000000 00000000		
00F02C _H			[R/W] 0 00000000 00000000		
00F030 _H to 00F03C _H		Rese	erved		
00F040 _H to 00F07C _H		Res	erved		Reserved
00F080 _H		BAD0 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	x	
00F084 _H		BAD1 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	X	
00F088 _H		BAD2 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	x	
00F08C _H		BAD3	[R/W] XXXXXXXX XXXXXXX	X	
00F090 _H		BAD4 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	x	EDSU / MPU
00F094 _H		BAD5 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	X	
00F098 _H		BAD6 XXXXXXXX XXXXXXXX		x	
00F09C _H		BAD7 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	x	
00F0A0 _H		BAD8 XXXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXXX	x	



Address	Register							
Address	+0	+1	+2	+3	Block			
00F0A4 _H	X	BAD9 XXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXX	xx				
00F0A8 _H	X	BAD10 [R/W] XXXXXXXX XXXXXXXX XXXXXXXX						
00F0AC _H	X	BAD11 [R/W] XXXXXXXX XXXXXXXX XXXXXXXX						
00F0B0 _H	X	BAD12 XXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXX	xx				
00F0B4 _H	X	BAD13 XXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXX	XX	EDSU / MPU			
00F0B8 _H	X	BAD14 XXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXX	XX				
00F0BC _H	X	BAD15 XXXXXXX XXXXXXXX	[R/W] XXXXXXXX XXXXXX	XX				
00F0C0 _H to		Rese	erved					
00F0FC _H								
00F100 _H to 02DFFC _H		Reserved						
02E000 _H to 02FFFC _H	CY91F463N	D-RAM 8 Kbytes						
030000 _H to	CY91	I/D-RAM 2 Kbytes						
0307FC _H 030800 _H to 0BFFFC _H	(IIIStru	ction access is 0 wait cyc	erved	t cycle)	Reserved			
0C0000 _H to 0DFFFC _H		ROMS04 area	ı (128 Kbytes)		Flash memory			
0E0000 _H to 0FFFF4 _H		ROMS05 area	ı (128 Kbytes)		256 Kbytes			
0FFFF8 _H		FM\ XXXX	/ [R] XXXX _H		December de Mantage			
0FFFFC _H		Reset/Mode Vector						
100000 _H to 147FFC _H		Rese	erved		Reserved			
148000 _H to 14FFFC _H		ROMS07 are	a (32 Kbytes)		Flash memory 32 Kbytes			
148000 _H to 4FFFFC _H		Rese	erved		Reserved			

^{1.} The lower 16 bits (DTC15 to DTC0) of DMACA0 to DMACA4 cannot be accessed in bytes.



14. Interrupt Source Table

	Interrupt	number	Interru	pt level	Inter	rupt vector	Resource
Interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number ^[1]
Reset	0	00	-	-	3FC _H	000FFFFC _H	-
Mode vector	1	01	-	-	3F8 _H	000FFFF8 _H	-
System reserved	2	02	-	-	3F4 _H	000FFFF4 _H	-
System reserved	3	03	-	-	3F0 _H	000FFFF0 _H	-
System reserved	4	04	-	-	3EC _H	000FFFEC _H	-
CPU supervisor mode (INT #5 instruction) [2]	5	05	-	-	3E8 _H	000FFFE8 _H	-
Memory protection exception [2]	6	06	-	-	3E4 _H	000FFFE4 _H	-
System reserved	7	07	-	-	3E0 _H	000FFFE0 _H	-
System reserved	8	08	-	-	3DC _H	000FFFDC _H	-
System reserved	9	09	-	-	3D8 _H	000FFFD8 _H	-
System reserved	10	0A	-	-	3D4 _H	000FFFD4 _H	-
System reserved	11	0B	-	-	3D0 _H	000FFFD0 _H	-
System reserved	12	0C	-	-	3CC _H	000FFFCC _H	-
System reserved	13	0D	-	-	3C8 _H	000FFFC8 _H	-
Undefined instruction exception	14	0E	-	-	3C4 _H	000FFFC4 _H	-
NMI request	15	0F	F _H 1	fixed	3C0 _H	000FFFC0 _H	-
External interrupt 0	16	10	ICR00	440	3BC _H	000FFFBC _H	0, 16
External interrupt 1	17	11	ICRUU	440 _H	3B8 _H	000FFFB8 _H	1, 17
External interrupt 2	18	12	ICR01	441	3B4 _H	000FFFB4 _H	2, 18
External interrupt 3	19	13	ICRUI	441 _H	3B0 _H	000FFFB0 _H	3, 19
External interrupt 4	20	14	ICR02	442	3AC _H	000FFFAC _H	20
External interrupt 5	21	15	ICRUZ	442 _H	3A8 _H	000FFFA8 _H	21
External interrupt 6	22	16	ICDO2	442	3A4 _H	000FFFA4 _H	22
External interrupt 7	23	17	ICR03	443 _H	3A0 _H	000FFFA0 _H	23
System reserved	24	18	ICR04	444	39C _H	000FFF9C _H	-
System reserved	25	19	ICR04	444 _H	398 _H	000FFF98 _H	-
System reserved	26	1A	ICDOE	445	394 _H	000FFF94 _H	-
System reserved	27	1B	ICR05	445 _H	390 _H	000FFF90 _H	-
External interrupt 12	28	1C	ICR06	446	38C _H	000FFF8C _H	-
External interrupt 13	29	1D	ICRUO	446 _H	388 _H	000FFF88 _H	-
System reserved	30	1E	ICB07	117	384 _H	000FFF84 _H	-
System reserved	31	1F	ICR07	447 _H	380 _H	000FFF80 _H	-
Reload timer 0	32	20	ICD00	440	37C _H	000FFF7C _H	4, 32
Reload timer 1	33	21	ICR08	448 _H	378 _H	000FFF78 _H	5, 33
Reload timer 2	34	22	ICBOO	440	374 _H	000FFF74 _H	34
Reload timer 3	35	23	ICR09	449 _H	370 _H	000FFF70 _H	35
System reserved	36	24	ICP10	111	36C _H	000FFF6C _H	36
System reserved	37	25	ICR10	44A _H	368 _H	000FFF68 _H	37



	Interrupt	number	Interru	pt level	Inter	Resource	
Interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number ^[1]
System reserved	38	26	ICR11	44D	364 _H	000FFF64 _H	38
Reload timer 7	39	27	ICKII	44B _H	360 _H	000FFF60 _H	39
Free-run timer 0	40	28	ICR12	440	35C _H	000FFF5C _H	40
Free-run timer 1	41	29	ICKIZ	44C _H	358 _H	000FFF58 _H	41
Free-run timer 2	42	2A	ICD12	440	354 _H	000FFF54 _H	42
Free-run timer 3	43	2B	ICR13	44D _H	350 _H	000FFF50 _H	43
System reserved	44	2C	ICD14	445	34C _H	000FFF4C _H	44
System reserved	45	2D	ICR14	44E _H	348 _H	000FFF48 _H	45
System reserved	46	2E	10045	445	344 _H	000FFF44 _H	46
System reserved	47	2F	ICR15	44F _H	340 _H	000FFF40 _H	47
System reserved	48	30	ICD4C	450	33C _H	000FFF3C _H	-
System reserved	49	31	ICR16	450 _H	338 _H	000FFF38 _H	-
System reserved	50	32	10047	454	334 _H	000FFF34 _H	-
System reserved	51	33	ICR17	451 _H	330 _H	000FFF30 _H	-
CAN 4	52	34	100.40	450	32C _H	000FFF2C _H	-
CAN 5	53	35	ICR18	452 _H	328 _H	000FFF28 _H	-
LIN-USART0 RX	54	36	10040	450	324 _H	000FFF24 _H	6, 48
LIN-USART0 TX	55	37	ICR19	453 _H	320 _H	000FFF20 _H	7, 49
LIN-USART1 RX	56	38	LODGO	454	31C _H	000FFF1C _H	8, 50
LIN-USART1 TX	57	39	ICR20	454 _H	318 _H	000FFF18 _H	9, 51
LIN-USART2 RX	58	3A	10004	455	314 _H	000FFF14 _H	52
LIN-USART2 TX	59	3B	ICR21	455 _H	310 _H	000FFF10 _H	53
LIN-USART3 RX	60	3C	LODGO	450	30C _H	000FFF0C _H	54
LIN-USART3 TX	61	3D	ICR22	456 _H	308 _H	000FFF08 _H	55
System reserved	62	3E	ICR23 ^[3]	457	304 _H	000FFF04 _H	-
Delayed interrupt	63	3F	ICR23 [e]	457 _H	300 _H	000FFF00 _H	-
System reserved [4]	64	40	(10004)	(450.)	2FC _H	000FFEFC _H	-
System reserved [4]	65	41	(ICR24)	(458 _H)	2F8 _H	000FFEF8 _H	-
System reserved	66	42	LODOS	450	2F4 _H	000FFEF4 _H	10, 56
System reserved	67	43	ICR25	459 _H	2F0 _H	000FFEF0 _H	11, 57
System reserved	68	44	LODGO	454	2EC _H	000FFEEC _H	12, 58
System reserved	69	45	ICR26	45A _H	2E8 _H	000FFEE8 _H	13, 59
System reserved	70	46	10007	455	2E4 _H	000FFEE4 _H	60
System reserved	71	47	ICR2/	ICR27 45B _H		000FFEE0 _H	61
System reserved	72	48	IODOO	450	2DC _H	000FFEDC _H	62
System reserved	73	49	ICR28	45C _H	2D8 _H	000FFED8 _H	63
I ² C 2	74	4A	ICDOO	450	2D4 _H	000FFED4 _H	-
I ² C 3	75	4B	ICR29	45D _H	2D0 _H	000FFED0 _H	-



	Interrupt	number	Interru	pt level	Interrupt vector		Resource
Interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number ^[1]
System reserved	76	4C	LODGO	455	2CC _H	000FFECC _H	64
System reserved	77	4D	ICR30	45E _H	2C8 _H	000FFEC8 _H	65
System reserved	78	4E	10004	455	2C4 _H	000FFEC4 _H	66
System reserved	79	4F	ICR31	45F _H	2C0 _H	000FFEC0 _H	67
System reserved	80	50	LODGO	400	2BC _H	000FFEBC _H	68
System reserved	81	51	ICR32	460 _H	2B8 _H	000FFEB8 _H	69
System reserved	82	52	LODGO	404	2B4 _H	000FFEB4 _H	70
System reserved	83	53	ICR33	461 _H	2B0 _H	000FFEB0 _H	71
System reserved	84	54	10004	400	2AC _H	000FFEAC _H	72
System reserved	85	55	ICR34	462 _H	2A8 _H	000FFEA8 _H	73
System reserved	86	56	LODOS	400	2A4 _H	000FFEA4 _H	74
System reserved	87	57	ICR35	463 _H	2A0 _H	000FFEA0 _H	75
System reserved	88	58	LODGO	404	29C _H	000FFE9C _H	76
System reserved	89	59	ICR36	464 _H	298 _H	000FFE98 _H	77
System reserved	90	5A	ICD27	405	294 _H	000FFE94 _H	78
System reserved	91	5B	ICR37	465 _H	290 _H	000FFE90 _H	79
Input capture 0	92	5C	ICD20	466	28C _H	000FFE8C _H	80
Input capture 1	93	5D	ICR38	466 _H	288 _H	000FFE88 _H	81
Input capture 2	94	5E	ICD20	467	284 _H	000FFE84 _H	82
Input capture 3	95	5F	ICR39	467 _H	280 _H	000FFE80 _H	83
System reserved	96	60	ICP40	460	27C _H	000FFE7C _H	84
System reserved	97	61	ICR40	468 _H	278 _H	000FFE78 _H	85
System reserved	98	62	ICD44	460	274 _H	000FFE74 _H	86
System reserved	99	63	ICR41	469 _H	270 _H	000FFE70 _H	87
Output compare 0	100	64	ICR42	464	26C _H	000FFE6C _H	88
Output compare 1	101	65	ICR42	46A _H	268 _H	000FFE68 _H	89
Output compare 2	102	66	ICR43	46B _H	264 _H	000FFE64 _H	90
Output compare 3	103	67	ICR43	40DH	260 _H	000FFE60 _H	91
System reserved	104	68	ICR44	460	25C _H	000FFE5C _H	92
System reserved	105	69	ICK44	46C _H	258 _H	000FFE58 _H	93
System reserved	106	6A	ICR45	460	254 _H	000FFE54 _H	94
System reserved	107	6B	101145	46D _H	250 _H	000FFE50 _H	95
System reserved	108	6C	ICR46	46E _H	24C _H	000FFE4C _H	-
Phase Frequency modulator	109	6D	101140	40⊏H	248 _H	000FFE48 _H	-
System reserved	110	6E	ICR47 ^[4]	46E	244 _H	000FFE44 _H	-
System reserved	111	6F	IUN4/ 1.1	46F _H	240 _H	000FFE40 _H	-
PPG0	112	70	ICR48	470	23C _H	000FFE3C _H	15, 96
PPG1	113	71	101140	470 _H	238 _H	000FFE38 _H	97



	Interrupt	t number	Interru	pt level	Inter	Resource	
Interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number ^[1]
PPG2	114	72	ICD40	474	234 _H	000FFE34 _H	98
PPG3	115	73	ICR49	471 _H	230 _H	000FFE30 _H	99
PPG4	116	74	ICDEO	470	22C _H	000FFE2C _H	100
PPG5	117	75	ICR50	472 _H	228 _H	000FFE28 _H	101
PPG6	118	76	ICDE1	472	224 _H	000FFE24 _H	102
PPG7	119	77	ICR51	473 _H	220 _H	000FFE20 _H	103
System reserved	120	78	IODEO	474	21C _H	000FFE1C _H	104
System reserved	121	79	ICR52	474 _H	218 _H	000FFE18 _H	105
System reserved	122	7A	ICDE2	475	214 _H	000FFE14 _H	106
System reserved	123	7B	ICR53	475 _H	210 _H	000FFE10 _H	107
System reserved	124	7C	ICDE4	470	20C _H	000FFE0C _H	108
System reserved	125	7D	ICR54	476 _H	208 _H	000FFE08 _H	109
System reserved	126	7E	ICDEE	477	204 _H	000FFE04 _H	110
System reserved	127	7F	ICR55	477 _H	200 _H	000FFE00 _H	111
Up/down counter 0	128	80	ICDEC	470	1FC _H	000FFDFC _H	-
Up/down counter 1	129	81	ICR56	478 _H	1F8 _H	000FFDF8 _H	-
System reserved	130	82	ICD57	470	1F4 _H	000FFDF4 _H	-
System reserved	131	83	ICR57	479 _H	1F0 _H	000FFDF0 _H	-
Real time clock	132	84	ICDE0	470	1EC _H	000FFDEC _H	-
Calibration unit	133	85	ICR58	47A _H	1E8 _H	000FFDE8 _H	-
A/D converter 0	134	86	ICDEO	47D	1E4 _H	000FFDE4 _H	14, 112
System reserved	135	87	ICR59	47B _H	1E0 _H	000FFDE0 _H	-
System reserved	136	88	ICD60	470	1DC _H	000FFDDC _H	-
System reserved	137	89	ICR60	47C _H	1D8 _H	000FFDD8 _H	-
Low voltage detection	138	8A	ICD61	47D	1D4 _H	000FFDD4 _H	-
System reserved	139	8B	ICR61	47D _H	1D0 _H	000FFDD0 _H	-
Time-base overflow	140	8C	ICD62	475	1CC _H	000FFDCC _H	-
PLL clock gear	141	8D	ICR62	47E _H	1C8 _H	000FFDC8 _H	-
DMA controller	142	8E	ICR63	47E	1C4 _H	000FFDC4 _H	-
Main OSC stability wait	143	8F	ICINOS	47F _H	1C0 _H	000FFDC0 _H	-
System reserved	144	90	-		1BC _H	000FFDBC _H	-
Used by the INT instruction	145 to 255	91 to FF	-	-	1B8 _H to 000 _H	000FFDB8 _H to 000FFC00 _H	-

^{1.}The peripheral resources to which RN (Resource Number) is assigned are capable of being DMA transfer activation sources. In addition, RN respectively corresponds to an IS (Input Source) of the DMAC channel control register A(DMACA0 to DMACA4), and the IS (Input Source) can be obtained by representing RN in a binary number and adding "1" to the head of it.

Document Number: 002-04604 Rev. *C Page 59 of 81

^{2.}Memory Protection Unit (MPU) support

^{3.}ICR23 can be switched to ICR47 by setting REALOS compatibility bit (address 0C03_H ISO[0]).

^{4.}Used by REALOS



15. Electrical Characteristics

Absolute Maximum Rating 15.1

Develope	Combal	Ra	ting	I I mit	Domonico
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage ^[1]	V _{CC}	V _{SS} - 0.5	V _{SS} + 6.0	V	
Analog power supply voltage ^[1]	AV _{CC}	V _{SS} - 0.5	V _{SS} + 6.0	V	[2]
Analog power supply voltage ^[1]	AVRH	V _{SS} - 0.5	V _{SS} + 6.0	V	[2]
Input voltage ^[1]	V _I	V _{SS} - 0.3	V _{CC} + 0.3	V	[3]
Analog pin input voltage ^[1]	V _{IA}	V _{SS} - 0.3	AV _{CC} + 0.3	V	
Output voltage ^[1]	Vo	V _{SS} - 0.3	V _{CC} + 0.3	V	[3]
Maximum clamp current	I _{CLAMP}	- 2.0	+2.0	mA	[4]
Total maximum clamp current	$\Sigma I_{CLAMP} $	-	20	mA	[4]
"L" level maximum output current	I _{OL}	-	10	mA	[5]
"L" level average output current	I _{OLAV}	-	4	mA	[6]
"L" level total maximum output current	ΣI_{OL}	-	100	mA	
"L" level total average output current	Σl _{OLAV}	-	50	mA	[7]
"H" level maximum output current	I _{OH}	-	- 10	mA	[5]
"H" level average output current	I _{OHAV}	-	- 4	mA	[6]
"H" level total maximum output current	Σl _{OH}	-	- 100	mA	
"H" level total average output current	ΣI_{OHAV}	-	- 20	mA	[7]
Power consumption	P _D	-	700	mW	
Operation temperature		-40	+105	°C	When using V _{CC} = 3.3 V
Operation temperature	T _A	-40	+85	°C	When using V _{CC} = 5.0 V
Storage temperature	Tstg	- 55	+ 125	°C	

Document Number: 002-04604 Rev. *C Page 60 of 81

^{1.} The parameter is based on $V_{SS} = AV_{SS} = 0.0 \text{ V}$. 2. AV_{CC} and AVRH must not exceed $V_{CC} + 0.3 \text{ V}$, for example, at power on. AV_{CC} must not exceed V_{CC} . 3. V_{I} and V_{O} must not exceed $V_{CC} + 0.3 \text{ V}$. However, when the maximum value of the current to the input or the current from the input is limited by using outside parts, I_{CLAMP} ratings are applied in place of V_I ratings.



4

- Corresponding pins: Pin name P29_0 to P29_7, P24_0 to P24_7, P22_0 to P22_3, P20_0 to P20_2, P20_4 to P20_6, P15_0 to P15_3, P17_0 to P17_7, P21_0 to P21_2, P21_4 to P21_6, P14_0 to P14_3
- Use within recommended operating conditions.
- Use at DC voltage (current).
- The + B signal is an input signal exceeding V_{CC} voltage. The + B signal should always be applied by connecting a limiting resistor between the + B signal and the microcontroller.
- The value of the limiting resistor should be set so that the current input to the microcontroller pin does not exceed rated values at any time regardless of instantaneously or constantly when the + B signal is input.
- Note that when the microcontroller drive current is low, such as in the low power consumption modes, the + B input potential can increase the potential at the VCC pin via a protective diode, possibly affecting other devices.
- Note that if the + B signal is input when the microcontroller is off (not fixed at 0 V), since the power is supplied through the pin, the microcontroller may operate incompletely.
- Note that if the + B signal is input at power-on, since the power is supplied through the pin, the power supply voltage may become the voltage at which a power-on reset does not work.
- Do not leave + B input pins open.

 Note that analog input/output pins can input the + B signal only at using as a port.
- 5. Maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.
- 6. Average output current is defined as the value of the average current flowing through any one of the corresponding pins for a 100 ms period.
- 7. Total average output current is defined as the value of the average current flowing through all of the corresponding pins for a 100 ms period.

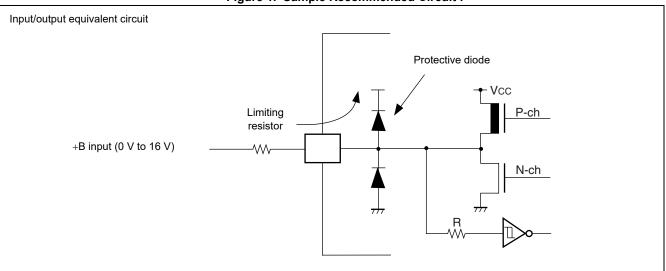


Figure 1. Sample Recommended Circuit:

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

Document Number: 002-04604 Rev. *C Page 61 of 81



15.2 Recommended Operating Conditions

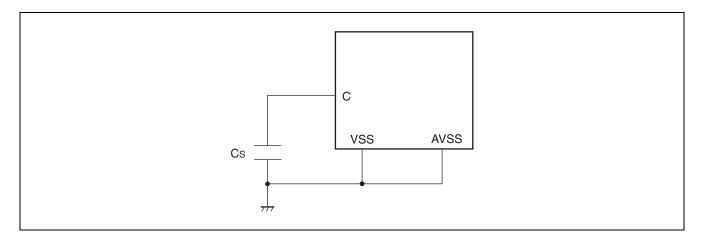
 $\left(V_{SS} = AV_{SS} = 0.0 \text{ V}\right)$

Parameter	Symbol	Va	lue	Unit	Remarks
raiailletei	Зуппоп	Min	Max	Oilit	Remarks
	V	3.0	3.6	V	When using V _{CC} = 3.3 V
Power supply voltage	V _{CC}	4.5	5.5	V	When using V _{CC} = 5.0 V
Power supply voltage	AV _{CC}	3.0	3.6	V	When using V _{CC} = 3.3 V
		4.5	5.5	V	When using V _{CC} = 5.0 V
Smoothing capacitor	C _S	4.7 (accuracy within ± 50%)		μF	Use a ceramic capacitor or a capacitor that has the similar frequency characteristics. Use a capacitor with a capacitance greater than C _S as the smoothing capacitor on the VCC pin.
Operating temperature	Т.	-40	+105	°C	When using V _{CC} = 3.3 V
Operating temperature	T _A	-40	+85	°C	When using V _{CC} = 5.0 V

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.





15.3 DC Characteristics

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \ V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \ T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} - 40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C)}$

Davamatav	Comple al	Din Nama	Condition		Value		I I m i 4	Domonto
Parameter	Symbol	Pin Name	Condition	Min	Тур	Max	Unit	Remarks
	V _{IHS}	Port pin	When CMOS hysteresis input type1 are selected	$0.7 \times V_{CC}$	-	V _{CC} + 0.3	V	
	V _{IHC}	Port pin	When CMOS hysteresis input type2 are selected	$0.8 \times V_{CC}$	-	V _{CC} + 0.3	V	
"H" level	V _{IHA}	Port pin	When Automotive inputs are selected	$0.8 \times V_{CC}$	-	V _{CC} + 0.3	V	
input voltage	V _{IHT}	Port pin	When TTL input levels are selected	2.0	-	V _{CC} + 0.3	V	
	V _{IH1}	MD2 to MD0	CMOS level input	$0.7 \times V_{CC}$	-	V _{CC} + 0.3	٧	
	V _{IH2}	MD3, INITX	CMOS hysteresis input	$0.7 \times V_{CC}$	-	V _{CC} + 0.3	V	
	V _{ILS}	Port pin	When CMOS hysteresis input type1 are selected	V _{SS} - 0.3	-	$0.3 \times V_{CC}$	V	
	V _{ILC}	Port pin	When CMOS hysteresis input type2 are selected	V _{SS} - 0.3	-	0.2 × V _{CC}	V	
"L" level	V _{ILA}	Port pin	When Automotive inputs are selected	V _{SS} - 0.3	-	0.5 × V _{CC}	V	
input voltage	V _{ILT}	Port pin	When TTL input levels are selected	V _{SS} – 0.3	-	0.8	V	
	V _{IL1}	MD2 to MD0	CMOS level input	V _{SS} – 0.3	-	0.3 × V _{CC}	V	
	V _{IL2}	MD3, INITX	CMOS hysteresis input	V _{SS} - 0.3	-	$0.3 \times V_{CC}$	V	
	V _{OH1}	Port pin	$V_{CC} = 5.0 \text{ V},$ $I_{OH} = -2.0 \text{ mA/}$ $V_{CC} = 3.3 \text{ V},$ $I_{OH} = -1.0 \text{ mA}$	V _{CC} – 0.5	-	-	V	[1]
"H" level output voltage	V _{OH2}	I ² C common port pin	$\begin{split} &V_{CC} = 5.0 \text{ V,} \\ &I_{OH} = -3.0 \text{ mA/} \\ &V_{CC} = 3.3 \text{ V,} \\ &I_{OH} = -3.0 \text{ mA} \end{split}$	V _{CC} – 0.5	-	-	V	
V _{OH3} Port pin		Port pin	$\begin{split} &V_{CC} = 5.0 \text{ V,} \\ &I_{OH} = -5.0 \text{ mA/} \\ &V_{CC} = 3.3 \text{ V,} \\ &I_{OH} = -3.0 \text{ mA} \end{split}$	V _{CC} – 0.5	-	-	V	[1]

Document Number: 002-04604 Rev. *C Page 63 of 81



 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \ V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \ T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} - 40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C)}$

Parameter	Symbol	Pin	Condition		Value		Unit	Remarks
raiailletei	Syllibol	name	Condition	Min	Тур	Max		Remarks
	V _{OL1}	Port pin	$\begin{split} &V_{CC} = 5.0 \text{ V}, \\ &I_{OH} = -2.0 \text{ mA/} \\ &V_{CC} = 3.3 \text{ V}, \\ &I_{OH} = -1.0 \text{ mA} \end{split}$	-	-	0.4	٧	[1]
"L" level output voltage	V _{OL2}	I ² C common port pin	$\begin{split} &V_{CC} = 5.0 \text{ V}, \\ &I_{OH} = -3.0 \text{ mA/} \\ &V_{CC} = 3.3 \text{ V}, \\ &I_{OH} = -3.0 \text{ mA} \end{split}$	-	-	0.4	٧	
	V _{OL3} Port pin		$\begin{split} &V_{CC} = 5.0 \text{ V}, \\ &I_{OH} = -5.0 \text{ mA/} \\ &V_{CC} = 3.3 \text{ V}, \\ &I_{OH} = -3.0 \text{ mA} \end{split}$	-	-	0.4	V	[1]
Input leak cur- rent	I _{IL}	1	$V_{CC} = AV_{CC} = 5.0 \text{ V},$ $V_{SS} < V_I < V_{CC}$	-5	-	+ 5	μΑ	
Pull-up resistance value	R_{UP}	Port pin	-	25	50	100	kΩ	
Pull-down resistance value	R _{DOWN}	Port pin	-	25	50	100	kΩ	



 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \ V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \ T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} - 40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

Davamatav	Cumbal	Pin	Condition		Value		Unit	Domouko
Parameter	Symbol	name	Condition	Min	Тур	Max	Unit	Remarks
	I _{CC3}	VCC	V _{CC} = 3.3 V CPU core: 80 MHz,	-	75	102	mA	$T_A = -40^{\circ}C \text{ to } +105^{\circ}C$
	I _{CC5}	VCC	V _{CC} = 5.0 V CPU core: 80 MHz,	-	75	102	mA	$T_A = -40$ °C to +85°C
	I _{CCS3}	VCC	V _{CC} = 3.3 V sleep mode	1	15	45	mA	
	I _{CCS5}	VCC	V _{CC} = 5.0 V sleep mode	-	15	45	mA	
	VCC	$V_{CC} = 3.3 \text{ V stop mode at using}$ RTC) [3]	-	100	550	μА	T _A = +25°C When the CR oscillator is operating and low voltage detection is enabled.	
	I _{CTS5}	VCC	$V_{CC} = 5.0 \text{ V}$ stop mode at using RTC) [3]	-	200	650	μА	T _A = +25°C When the CR oscillator is operating and low voltage detection is enabled.
	І _{сснз}	VCC	V _{CC} = 3.3 V stop modeoscillation stop) ^[4]	-	100	500	μА	T _A = +25°C When the CR oscillator is stopping and low voltage detection is enabled.
	I _{CCH5}	VCC	V _{CC} = 5.0 V stop modeoscillation stop) ^[4]	-	150	600	μА	T _A = +25°C When the CR oscillator is stopping and low voltage detection is enabled.
	I _{CCF}	VCC	Flash programming (Write/Erase)	-	25	50	mA	[2]
Input capacitance	C _{IN}	Except VCC, AVCC, VSS, AVSS	-	-	5	15	pF	

^{1.} The drive power varies depending on the power supply voltage (3.3 V, 5.0 V).

Document Number: 002-04604 Rev. *C Page 65 of 81

^{2.} The power supply current when writing or erasing by executing the automatic algorithm.

^{3.} When the main clock oscillator is stopped and CR oscillator is operating (using the CR oscillator clock in the RTC) and the low voltage detection is enabled.

^{4.} When the main clock oscillator is stopped, the CR oscillator is stopped and the low voltage detection is enabled.



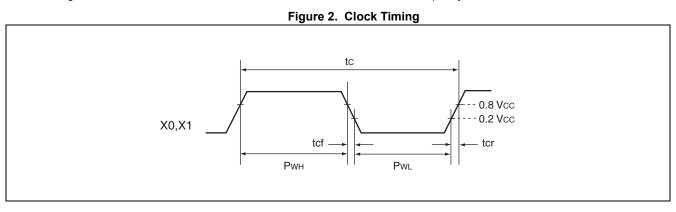
15.4 AC Characteristics

15.4.1 Clock Timing

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \ V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \ T_{A} = -40 ^{\circ}\text{C to } + 125 ^{\circ}\text{C/} - 40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

Parameter	Sym-	Pin Name	Condi-		Value		Unit	Remarks
Parameter	bol		tion	Min	Тур	Max	Oilit	Remarks
Clock fraguency	_	V0 V1		3.5	4	16	MHz	When using the oscillator circuit
Clock frequency	F _C	X0, X1		3.5	-	32	MHz	When using an external clock
Clock cycle time		X0, X1		62.5	-	285.7	ns	When using the oscillator circuit
Clock cycle time	t _C	λ0, λ1		31.25	-	285.7	ns	When using an external clock
Internal operation clock	F _{CP}	-	-	-	-	80	MHz	CPU clock, when using PLL ^[1]
frequency	F _{CPP}	-		-	-	40	MHz	Peripheral clock
Internal operation clock cycle	t _{CP}	-		12.5	-	-	ns	CPU clock, when using PLL
time	t _{CPP}	-		25	-	-	ns	Peripheral clock
Input clock pulse width	P _{WH,} P _{WL}	X0		30	-	-	ns	
Input clock rise/fall time	tcf, tcr	X0		-	-	5	ns	

^{1.} When using the clock modulator, set such that the maximum value of the modulated frequency is 96 MHz or less.



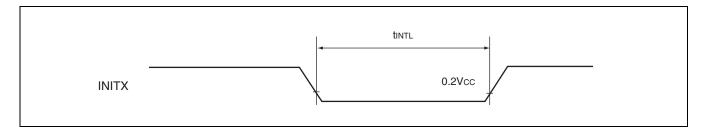
Page 67 of 81



15.4.2 Reset Input

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ } V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \text{ } T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} -40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

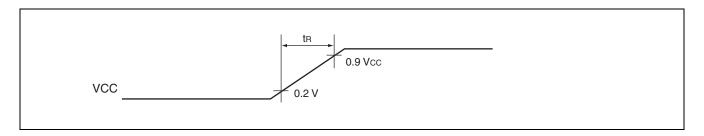
Parameter	Symbol	Pin Name	Condition	Value	Unit		
raiailletei	Syllibol	Fill Name	Condition	Min	Max	Ollit	
INITX input time (at power-on or stop mode)		4 INITY		Oscillation stabilization time of oscillator + 2.6	-	ms	
INITX input time (other than the above)	^τ INTL	INITX	-	20	-	μS	



15.4.3 Specification for Power-on

 $\left(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ } V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \text{ } T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} - 40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C} \right)$

Parameter	Symbol	Pin Name	Condition	Valu	Unit	
raidilletei	Syllibol	Min		Min	Max	Oilit
Power supply rising time	t _R	VCC	-	0.1	100	ms
Power supply start time	-	-	-	0.2	-	V
Power supply end time	-	-	-	-	0.9 × V _{CC}	V





15.4.4 LIN-USART Timing

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ } V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \text{ } T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} -40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

Downwater	Comphal	Din Name	Condition	Va	lue	I Incit
Parameter	Symbol	Pin Name	Condition	Min	Max	Unit
Serial clock cycle time	t _{SCYC}	SCK0 to SCK3		8 × t _{CLKP}	-	ns
SCK ↓→ SOT delay time	t _{SLOV}	SCK0 to SCK3, SOT0 to SOT3	Internal shift alsold	- 80	+ 80	ns
Valid SIN → SCK ↑	t _{IVSH}	SCK0 to SCK3, SIN0 to SIN3	Internal shift clock mode	100	-	ns
SCK ↑→ valid SIN hold time	t _{SHIX}	SCK0 to SCK3, SIN0 to SIN3		60	-	ns
Serial clock "H" pulse width	t _{SHSL}	SCK0 to SCK3		$4 \times t_{CLKP}$	-	ns
Serial clock "L" pulse width	t _{SLSH}	SCK0 to SCK3]	$4 \times t_{CLKP}$	-	ns
$SCK \downarrow \rightarrow SOT$ delay time	t _{SLOV}	SCK0 to SCK3, SOT0 to SOT3	External shift	-	150	ns
Valid SIN → SCK ↑	t _{IVSH}	SCK0 to SCK3, SIN0 to SIN3	clock mode	60	-	ns
SCK ↑→ Valid SIN hold time	t _{SHIX}	SCK0 to SCK3, SIN0 to SIN3		60	-	ns

Notes:

- Above values are AC characteristics for CLK synchronous mode.
- \blacksquare t_{CLKP} is the cycle time of the peripheral clock.

Document Number: 002-04604 Rev. *C Page 68 of 81



Figure 3. Internal Shift Clock Mode

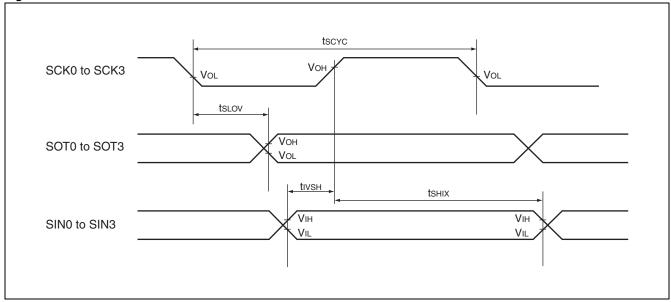
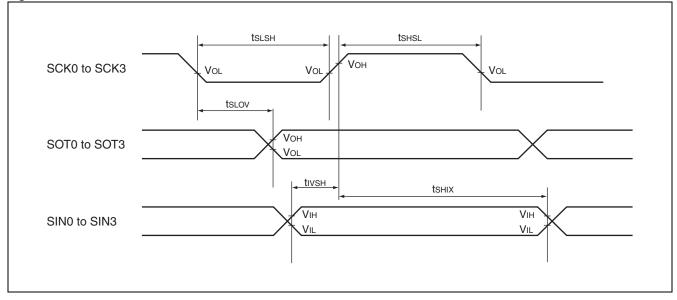


Figure 4. External Shift Clock Mode



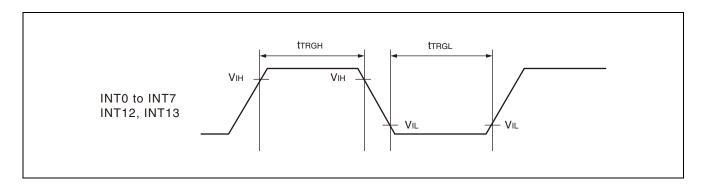


15.4.5 Trigger Input Timing

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ } V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \text{ } T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} -40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin Name	Va	Unit		
Parameter	Зуппоп	FIII Naille	Min	Max	Offic	
External interrupt input pulse width	t _{TRGH}	INT0 to INT7 INT12, INT13	4 × t _{CLKP}	-	ns	

Note: t_{CLKP} is the cycle time of the peripheral clock.

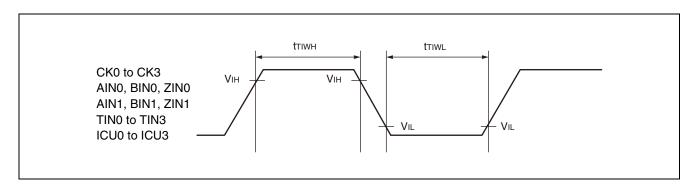


15.4.6 Timer Related Resource Input Timing

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ } V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \text{ } T_{A} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C/} -40 ^{\circ}\text{C to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin Name	Va	Unit	
Farameter	Symbol	FIII Name	Min	Max	Oilit
Free-run timer input clock pulse width		CK0 to CK3	4 × t _{CLKP}	_	ns
Up/down counter input pulse width	t _{TIWH}	AINO, AIN1 BINO, BIN1 ZINO, ZIN1	4 × t _{CLKP}	-	ns
Reload timer input pulse width		TIN0 to TIN3	4 × t _{CLKP}	-	ns
Input capture input pulse width	1	ICU0 to ICU3	4 × t _{CLKP}	=	ns

Note: t_{CLKP} is the cycle time of the peripheral clock.



Document Number: 002-04604 Rev. *C Page 70 of 81



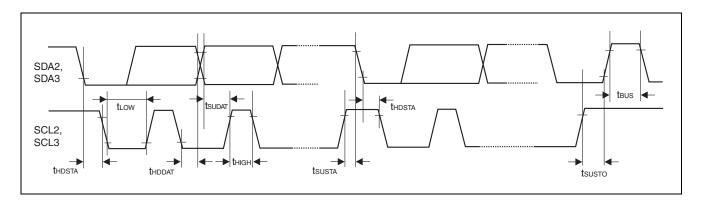
15.4.7 I²C Timing

(V_{CC} = 3.0 V to 3.6 V/ 4.5 V to 5.5 V, V_{SS} = AV_{SS} = 0 V, T_A = -40 °C to + 105 °C/-40 °C to + 85 °C)

Parameter	Symbol	Pin Name	Condition	Standaı	d Mode	Fast M	ode ^[1]	Unit
i didiletei	Cymbol		Condition	Min	Max	Min	Max	Oiiit
SCL clock frequency	f _{SCL}			0	100	0	400	kHz
"L" width of the SCL clock	t _{LOW}			4.7	-	1.3	-	μS
"H" width of the SCL clock	t _{HIGH}			4.0	-	0.6	-	μS
Bus free time between STOP and START conditions	t _{BUS}		$R = 1 \text{ k}\Omega,$ $C = 50 \text{ pF}^{[2]}$	4.7	-	1.3	-	μS
SCL ↑→ SDA output delay time	t _{DLDAT}			=	5 × t _{CLKP}	=	5 × t _{CLKP}	ns
Setup time for a repeated START condition SCL $\uparrow \rightarrow$ SDA \downarrow	t _{SUSTA}	SDA2, SDA3, SCL2,		4.7	-	0.6	-	μS
Hold time for a repeated START condition SDA ↓→ SCL↓	t _{HDSTA}	SCL3	C = 50 pr	4.0	=	0.6	-	μS
Setup time for STOP condition SCL $\uparrow \rightarrow$ SDA \uparrow	t _{susto}			4.0	-	0.6	-	μS
SDA data input hold time SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$	t _{HDDAT}			2 × t _{CLKP}	=	2 × t _{CLKP}	-	μS
SDA data input setup time SDA $\downarrow\uparrow$ \rightarrow SCL \uparrow	t _{SUDAT}			250	=	100	=	ns

^{1.} For use at over 100 kHz, set the peripheral clock to at least 6 MHz.

Note: t_{CLKP} is the cycle time of the peripheral clock.



Document Number: 002-04604 Rev. *C Page 71 of 81

^{2.} R and C are the pull-up resistance and load capacitance of the SCL and SDA lines.



15.5 Electrical Characteristics for A/D Converter

(V_{CC} = 3.0 V to 3.6 V/ 4.5 V to 5.5 V, V_{SS} = AV_{SS} = 0 V, T_A = -40 °C to + 105 °C/-40 °C to + 85 °C)

Downwater	Cumbal	Din Nama		l lm!4	Damanka		
Parameter	Symbol	Pin Name	Min	Тур	Max	Unit	Remarks
Resolution	-	-	-	-	10	bit	
Total error ^[1]	-	-	-	-	± 3	LSB	
Linearity error ^[1]	-	-	-	-	± 2.5	LSB	
Differential linearity error ^[1]	-	-	-	-	± 1.9	LSB	
Zero transition voltage ^[1]	V _{OT}	AN0 to AN7	AV _{SS} -1.5 LSB	AV _{SS} -0.5 LSB	AV _{SS} -2.5 LSB	V	
Full scale transition voltage ^[1]	V _{FST}	AN0 to AN7	AVRH-3.5 LSB	AVRH-1.5 LSB	AVRH-0.5 LSB	V	
Conversion time			1 ^[2]	_	=	μS	Using at 5 V
Conversion time	_	-	3 [2]	_	=	μS	Using at 3.3 V
Analog port input current	I _{AIN}	AN0 to AN7	=	_	10	μА	
Analog input voltage	V _{AIN}	AN0 to AN7	AV _{SS}	_	AVRH	V	
Reference voltage	=	AVRH	AV _{SS}	_	AV _{CC}	V	
Analog power supply current (analog + digital)	I _A	AVCC	-	2.4	4.7	mA	Including reference supply
Reference voltage supply current	I _R	AVRH	-	0.65	1.0	mA	
Analog input equivalent capacitance	Cin	AN0 to AN7	-	-	8.5	pF	
Analog input equivalent	Rin	AN0 to AN7	-	-	2.6	kΩ	AVcc ≥ 4.5 V
resistance	KIII	AINU IO AIN7	-	-	12.1	kΩ	AVcc ≥ 3.0 V
Output impedance of analog signal source	Rext	=	-	-	4.2	kΩ	

^{1.} Measured in the CPU sleep state

Document Number: 002-04604 Rev. *C Page 72 of 81

^{2.} Set no shorter than this time period in the peripheral clock and conversion setting register



15.6 Notes on the A/D Converter

The diagram below shows the equivalent circuit of the sampling circuit in the A/D converter.

Apply the output impedance in the external circuit for the analog output under the following conditions.

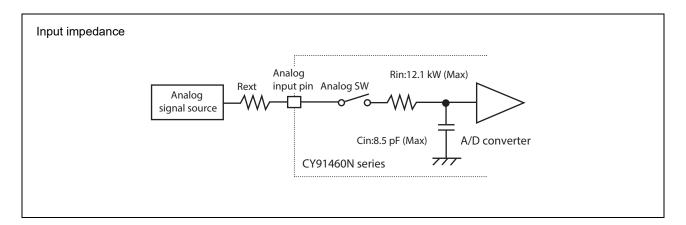
- The recommended output impedance for the external circuit is $4.2 \text{ k}\Omega$ or less.
- If an external capacitor is used, remember to consider the capacitive voltage divider effect due to the external capacitor and the internal capacitor in the chip. Accordingly, an external capacitance several thousand times that of the internal capacitance is recommended.
- The analog voltage sampling period may be too short if the output impedance of the external circuit is high.In this case, select Rext and Tsamp to satisfy the following condition.

Rext = Tsamp/ $(7 \times Cin)$ – Rin

Rext: Output impedance of the analog signal source

Tsamp: Sampling time

Cin: Equivalent capacitance of analog input
Rin: Equivalent resistance of analog input





15.7 Definition of A/D Converter Terms

■ Resolution

Analog variation that is recognizable by an A/D converter.

■ Linearity error

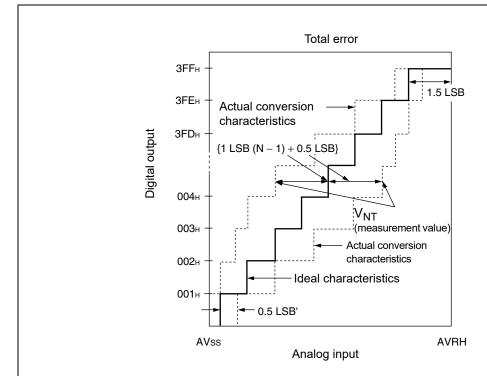
Deviation between actual conversion characteristics and a straight line connecting zero transition point (00 0000 0000 \leftrightarrow 00 0000 0001) and full scale transition point (11 1111 1110 \leftrightarrow 11 1111 1111).

■ Differential linearity error

Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.

■ Total error

This error indicates the difference between actual and theoretical values, including the zero transition error/full scale transition error/linearity error.



1LSB' (ideal value) =
$$\frac{AVRH - AV_{SS}}{1024}$$
 [V]

Total error of digital output N =
$$\frac{V_{NT} - \{1 \text{ LSB'} \times (N-1) + 0.5 \text{ LSB'}\}}{1 \text{ LSB'}}$$

N: A/D converter digital output value

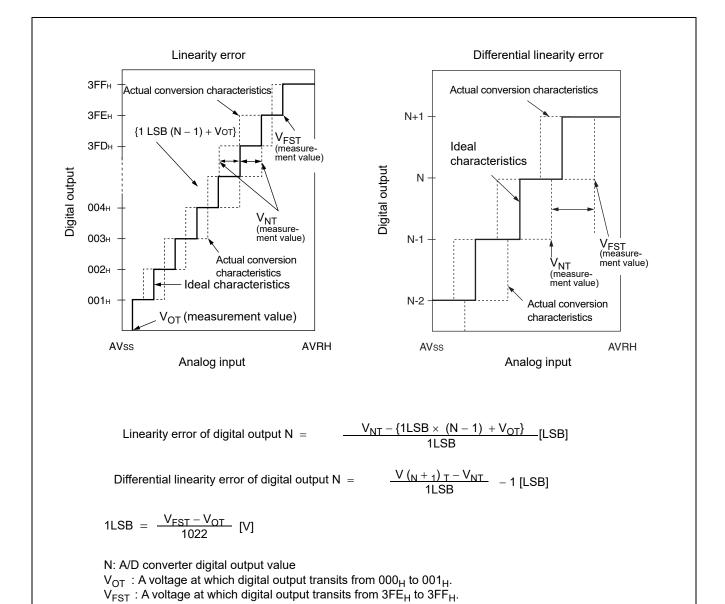
 V_{OT} ' (ideal value) = $AV_{SS} + 0.5 LSB' [V]$

V_{FST}' (ideal value) = AVRH - 1.5 LSB' [V]

 V_{NT} : A voltage at which digital output transits from (N + 1) to N

(Continued)







15.8 Flash Memory Program/Erase Characteristics

Parameter	Conditions	Value		Unit	Remarks	
raiailletei	Conditions	Min	Тур	Max	Onit	Remarks
Sector erase time		=	0.9	3.6	s	Excludes programming prior to erasure
Chip erase time	$T_A = +25 ^{\circ}C$	=	9	=	s	Excludes programming prior to erasure
Word (16-bit width) programming time	$V_{CC} = 5.0 \text{ V}$	=	23	370	μs	Except for the overhead time of the system level
Program/Erase cycle	-	10000	=	=	cycle	
Flash memory data retention time	Average T _A = +85 °C	20	-	-	year	[1]

^{1.} The value is translated high-temperature measurement results of the technology reliability evaluation into average value at + 85 °C.

Document Number: 002-04604 Rev. *C Page 76 of 81

Page 77 of 81

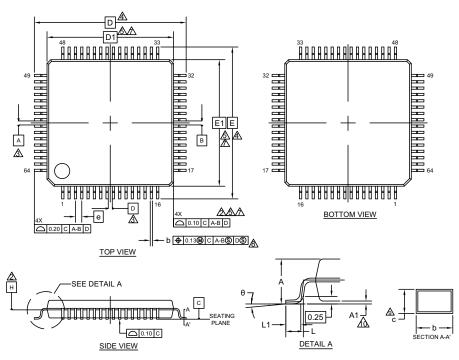


16. Ordering Information

Part Number	Package	Remarks
CY91F463NAPMC-GS-UJE1	64-pin plastic LQFP (LQG064)	Lead-free package
CY91F463NCPMC-GS-UJE1	64-pin plastic LQFP (LQG064)	Lead-free package



17. Package Dimension



SYMBOL	DIMENSION		
STIVIBOL	MIN.	NOM.	MAX.
А			1.70
A1	0.00		0.20
b	0.27	0.32	0.37
С	0.09		0.20
D	14	4.00 BS	С
D1	12	2.00 BS	С
е	C	.65 BS	2
E	14	4.00 BS	С
E1	12	2.00 BS	С
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°		8°

NOTES

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- ADATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
- ⚠DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
- TO BE DETERMINED AT SEATING PLANE C.
- ⚠ DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE.
 DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
- ⚠ DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
- REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
- ⚠ DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-13881 **

PACKAGE OUTLINE, 64 LEAD LQFP 12.0X12.0X1.7 MM LQG064 REV**



18. Main Changes in This Edition

Spansion Publication Number: DS07-16607-4E

Page	Section	Change Results
-	-	Changed the part number. MB91F463NB → MB91F463NC
11	I/O Circuit Type Type J	Corrected "invertor for clock input (Xout)" to "hysteresis type".
35	Memory Space	Added the sector configuration for MB91F463NC in "3. flash memory sector configuration".
81	Ordering Information	Changed the part number. MB91F463NBPMC → MB91F463NCPMC-GSE1

NOTE: Please see "Document History" for later revised information.

Page	Section	Change Results
Rev.*B		
-	Marketing Part Numbers changed from an MB	prefix to a CY prefix
2, 6, 77, 78	Features 2. Pin Assignment 16. Ordering Information 17. Package Dimensions	Package description modified to JEDEC description. FPT-64P-M23→ LQG064
77	16. Ordering Information	Revised Marketing Part Numbers as follows: Before) - MB91F463NCPMC-GSE1 After) - CY91F463NCPMC-GS-UJE1 Added Marketing Part Numbers as follows: - CY91F463NAPMC-GS-UJE1

Document Number: 002-04604 Rev. *C Page 79 of 81



Document History

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	_	AKIH	06/29/2009	Migrated to Cypress and assigned document number 002-04604. No change to document contents or format.
*A	5208752	AKIH	04/07/2016	Updated to Cypress template
*B	6168325	WAFA	05/15/2018	Revised the following items: Marketing Part Numbers changed from an MB prefix to a CY prefix. Features 2. Pin Assignment 16. Ordering Information 17. Package Dimensions For details, please see 18. Main Changes in This Edition.
*C	6550103	ATSE	04/19/2019	Revised the following item; 15.7 Definition of A/D Converter Terms Differential linearity error of digital output N Before) {V(N+1)T - VNT}/1LSB After) {V(N+1)T - VNT}/1LSB - 1

Document Number: 002-04604 Rev. *C Page 80 of 81



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